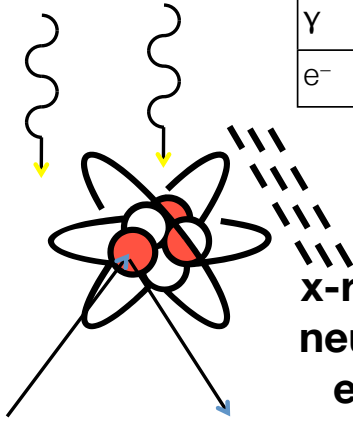


X-ray Detection

	Brightness	Mean Free Path	Absorption Length	Spatial Resolution
	/cm ² /sr/eV	nm	nm	nm
n	10 ¹⁴	10 ⁷	10 ⁸	10 ⁶
γ	10 ²⁶	10 ³	10 ⁵	10 ¹
e ⁻	10 ²⁹	10 ¹	10 ³	0.05



x-ray scattering (probe electronic states)
neutron scattering (probe nuclear states)
electron microscopy (focus, Coulomb interactions)



Peter Denes
Lawrence Berkeley National Laboratory

P. Denes ♦ National School on Neutron and X-ray Scattering ♦ Argonne August 2012

Outline

- Basic concepts
 - “phenomenological”
 - Field of “detectors” is a bit more than 100 years old.
 - Can’t cover everything
 - Lots of terminology, much of it outdated
 - what can be measured
 - or so you think!
 - Types of detectors
 - With emphasis on semiconductor detectors
 - Silicon imaging detectors (what I do)



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Legend



Concept

- Detector concepts
 - 1D, 2D; Direct, Indirect; Counting, Integrating; spatial and temporal performance



Detection

- Detection concepts
 - Physics of the detector



Electronics

- Electronics



Detector

- All of the above



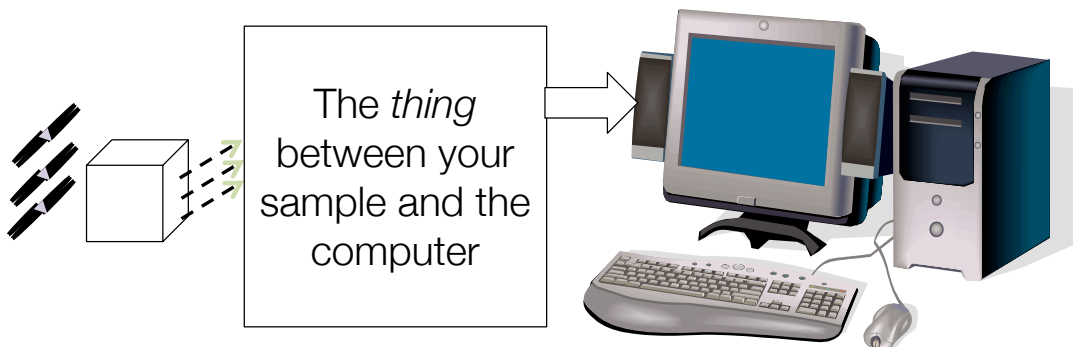
Data

- Data



Concept

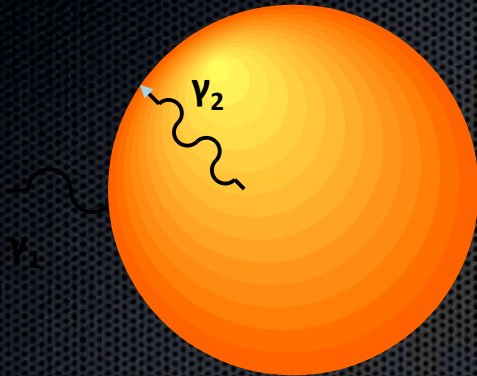
“Detector”



Distinguish between detector systems that fit the picture above (i.e. they have an ~ immediate electronic output) and those that are indirect (or use human processing)



Ideal Detector



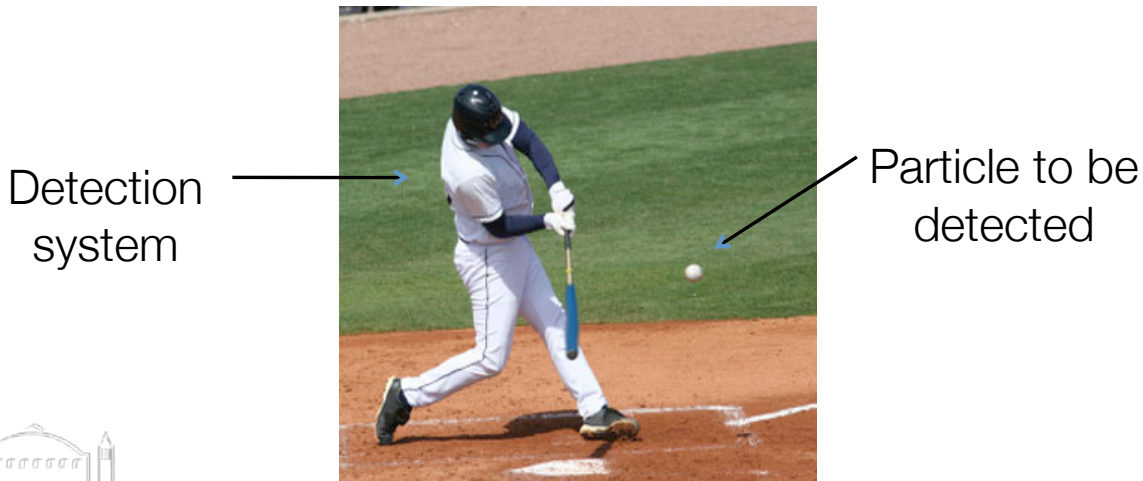
- Spatial information
 - $(x, y)_{\gamma_2}$
- Temporal information
 - $t(\gamma_2)$
- Energy information
 - E_{γ_2}
- With
 - High efficiency
 - $P_{\text{DETECT}}(\gamma_2) = 1$
 - 4π solid angle
 - low cost



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Spatial Detectors

- “Count ‘hits’”
- Spatial (or temporal) distribution
- “0”, “1”, “2” dimensional detectors



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Quantum Efficiency

Baseball:
Batting Average = hits / at bats

Particle detection:
Quantum efficiency = detected / incident quanta



Note that the Q.E. may depend on the energy of the incident quanta (we'll come back to this)



Timing and Energy Resolution

- Our example has timing resolution
 - $\sigma(t)$ is pretty good
 - $\epsilon(t)$ may not be that good
- Our example also has energy resolution
 - $\sigma(E)$ more complicated



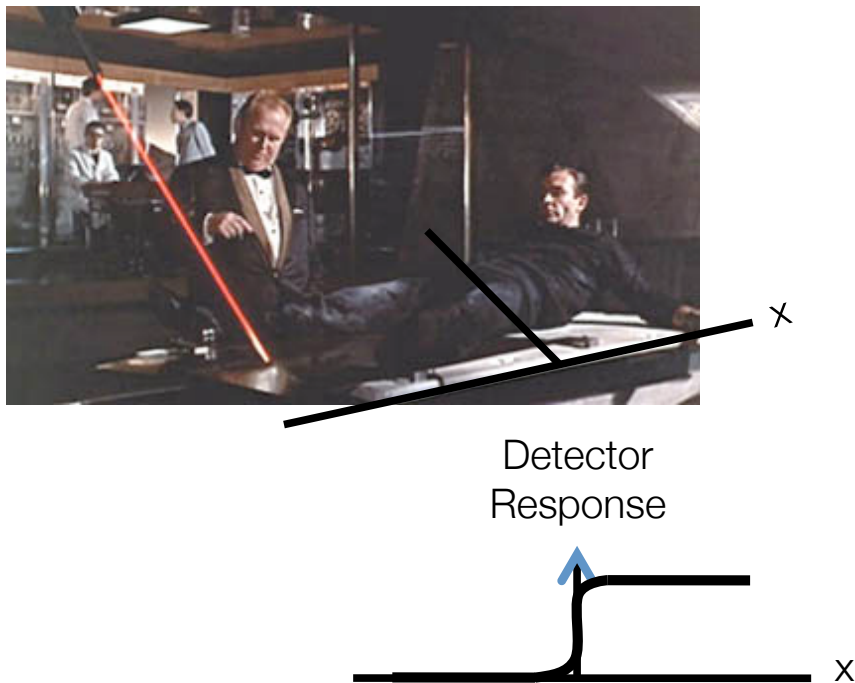
Calorimetric Photon Detector



Calorimetric detector: absorbed energy measured by change of temperature
(more generally, "calorimeters" measure total absorbed energy)
[superconducting calorimetric detectors]

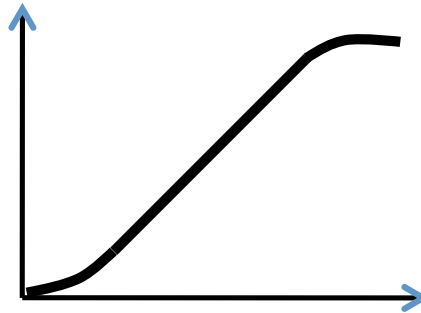
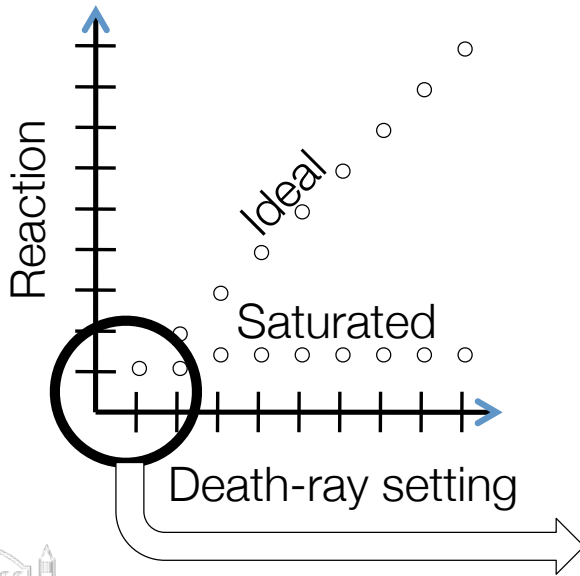


Detector Behavior



Detector Linearity

e.g. diffraction



Spatial Detector Properties

A “point” detector (“OD”)
Responds to hits in sensitive
area



No way to know where in the
sensitive area the hit occurred

There may be additional
information



Day-to-day oD Detector Example

Airport (pulsed induction)
metal detector



“yes / no” – along with
additional information



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Day-to-day 1D Example



Theory



Experiment



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Day-to-day 2D Detector Example



$$v = \Delta x / \Delta t$$



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An Example 2D Detector



- 2D arrangement of our 0D detector elements
- Which are quite non-linear
- Arranged in random sizes and orientations
- But with each element very small



Early X-ray Detection

Herr Röntgen

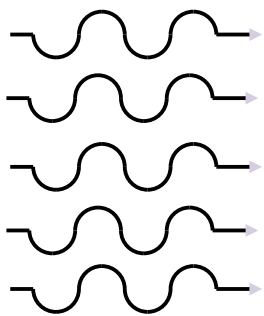


Frau Röntgen



Schematic of Experiment

Incident Radiation



Variable Density Attenuator



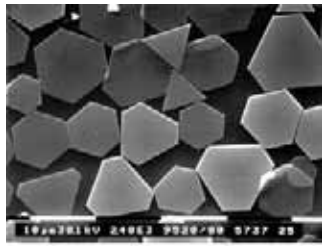
Detector



Image



The Detector – Photographic Film*

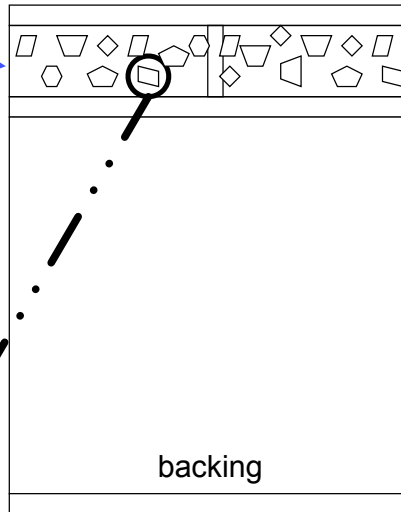


Electron micrograph of tabular grain emulsion

AgX + gelatin
(emulsion)



Silver halide emulsion on tri-acetate backing



sub-micron to few micron grains

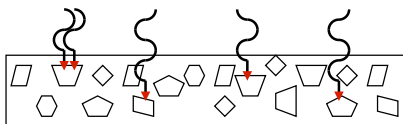


*Primitive, but still unbeaten for certain things

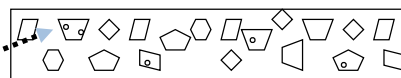
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How it Works

Incident light



phototelectrons convert Ag^+ sites to Ag^0 – at the same time, thermal fluctuations tend to “erase” the image. Generally, a few (visible) photons are required to leave a “latent” image on a grain

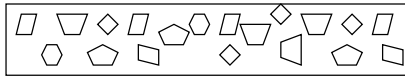


larger grains have larger cross section, so they are more likely to get hit. Thus, larger grains are “faster” but “grainier”



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How it Works



“develop” the image so that the sensitized AgX is reduced to black metallic silver



“fix” the image – removing the unexposed AgX



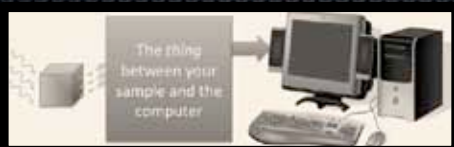
The chemistry and physics of photographic film is not trivial

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Spatial Imaging Characteristics - PSF



- Point Spread Function
 - δ -function input
 - $PSF(x_o, y_o, x_i, y_i)$
- Image is convolution of input at PSF
- “Black box” PSF includes all effects that might broaden or scatter the input



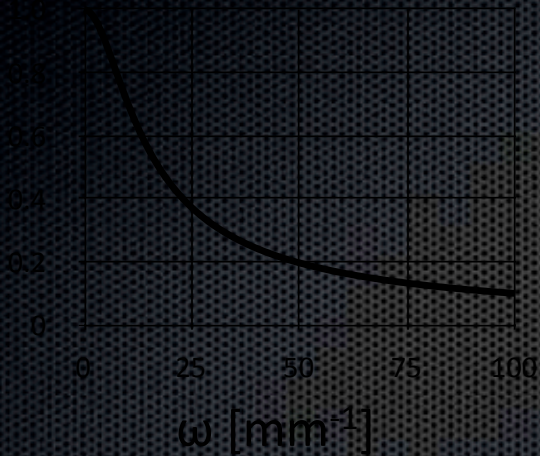
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Spatial Imaging Characteristics – MTF

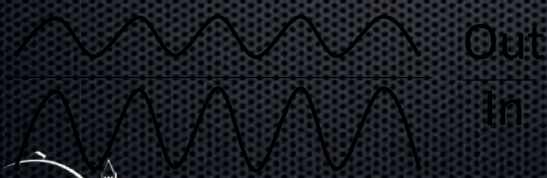


- Modulation Transfer Function
 - $\sin \omega x$ input
 - $MTF(\omega)$
 - $MTF(\omega_x, \omega_y)$
- $MTF = |FT(PSF)|$
- Related to contrast

MTF

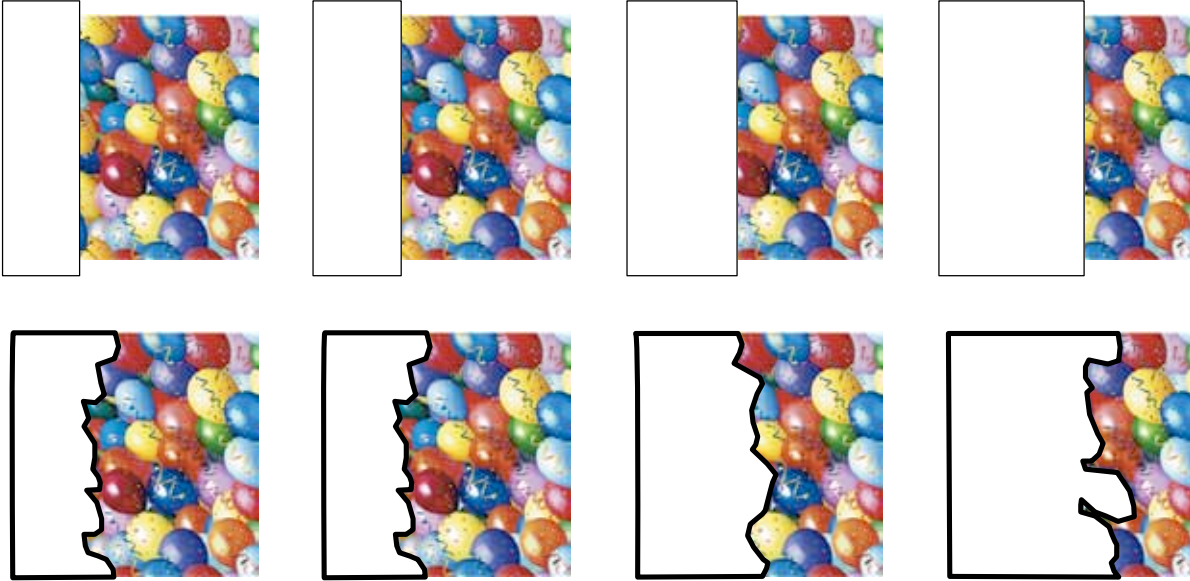


- Spatial analog to (temporal) frequency response in electronics
 - “Signal processing” also possible
 - e.g. early days of Hubble Space Telescope



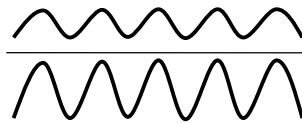
Consider ...

Stepping a knife edge across the film



Spatial Detector Concepts

- Quantum Efficiency
 - Active area
- Contrast (PSF, MTF)
 - Spatial (frequency dependence)



PSF = 0*



PSF = 1%



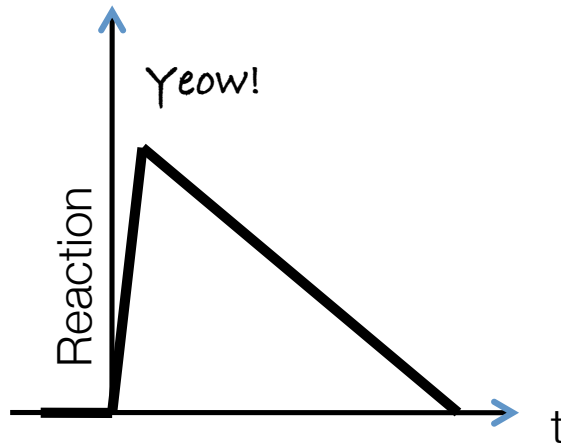
PSF = 5%

*of full image dimension

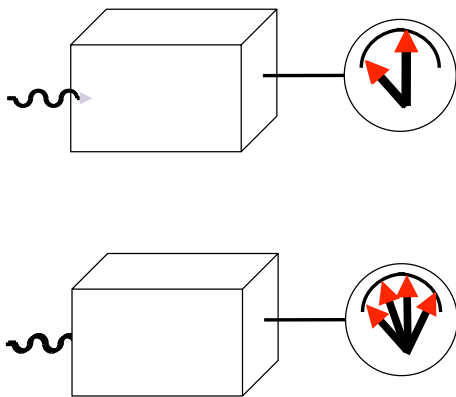


Detector Temporal Response

Pulsed Operation



“Counting” and “Integrating”



Consider temporal characteristics of

- source
- detector

“Counting” and “Integrating”

● $\Delta t (\gamma_1, \gamma_2) \gg \tau_{\text{DETECTOR}}$, and $P(N_\gamma > 1) \ll 1$

● Detector “counts” single photons

● $\Delta t (\gamma_1, \gamma_2) \gg \tau_{\text{DETECTOR}}$, and $P(N_\gamma > 1) \ll 1$ and

detector can quantize N_γ

● Detector “counts” single photons

● $\Delta t (\gamma_1, \gamma_2) \ll \tau_{\text{DETECTOR}}$

● Measure a “current” $\langle I \rangle = \langle dq/dt \rangle$

● Example: ALS $\Delta t_{\text{BUNCH}} = 2 \text{ ns}$, LCLS $\Delta t_{\text{BUNCH}} = 8 \text{ fs}$ →

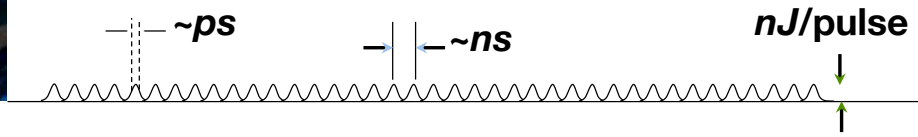


Storage Rings and FELs

Storage Rings



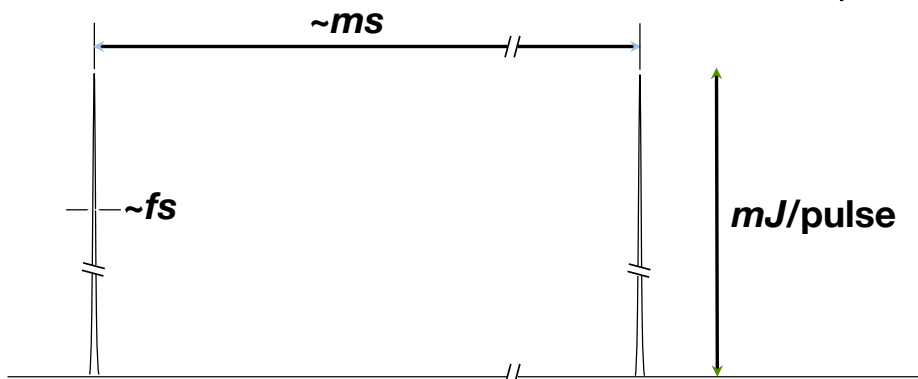
ALS



FELs



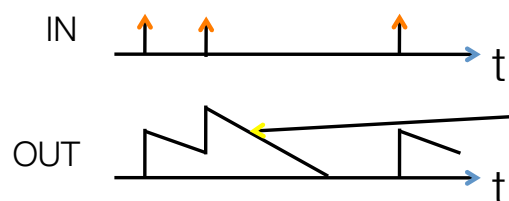
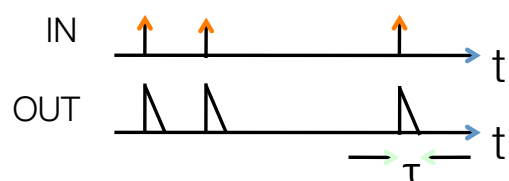
LCLS



FEL detector can not count individual photons (they all arrive at the same time)



Pileup, Double Pulse Resolution



Pileup
May or may not be a problem
(can recover with signal
processing)

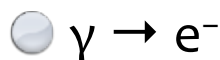
If photons arrive synchronously, maximum rate $\sim 1/\tau$

If photons arrive at random, maximum rate $\sim 1/10\tau$



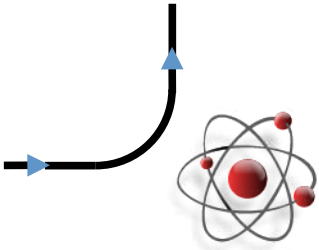
Look Further Into “Detector”

- Rarely does a (practical) photon detector actually detect photons
- Generally the photon is converted into one (or more) secondary particles
- Those secondary particles (usually electrons) are then detected, or create tertiary particles which are detected

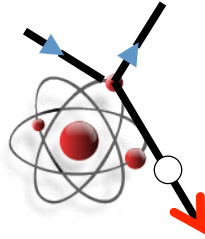


X-ray Interaction in Detector

Practically speaking, 3 possibilities:

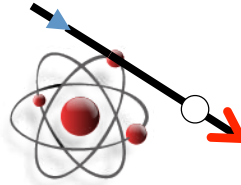


Elastic Scattering



Compton Scattering

$$E_e \neq E_\gamma$$



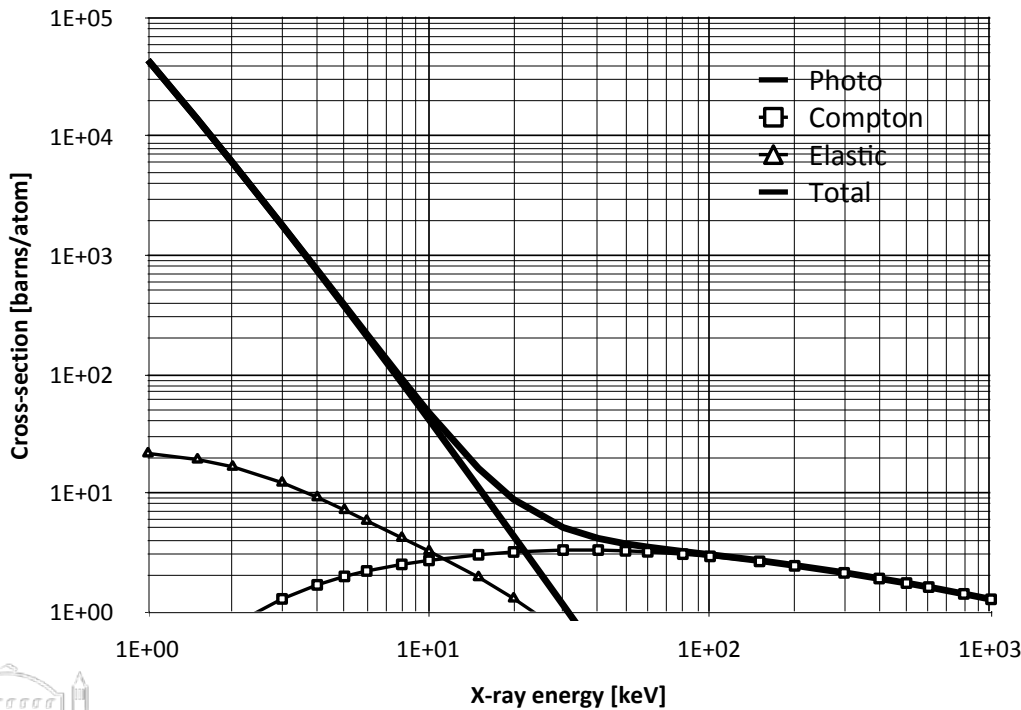
Photoelectric Absorption

$$E_e = E_\gamma$$



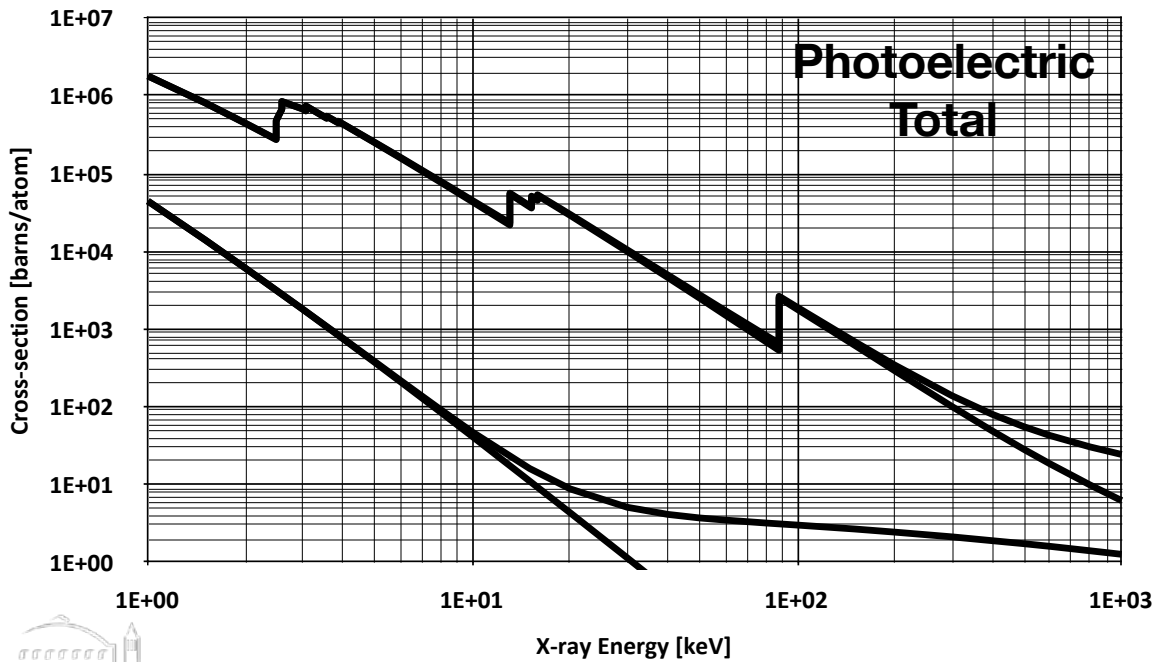
Electron range (very crudely) $R [\mu m] \approx E [keV]$

X-ray cross-section in Carbon



X-ray cross-sections in Carbon and Lead

For detector, high σ and all photoelectric



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Effect of Z (Detector) and E

The only thing photons are good for is to make electrons

Photoelectric Absorption:

$$\sigma \sim Z^n/E^3$$

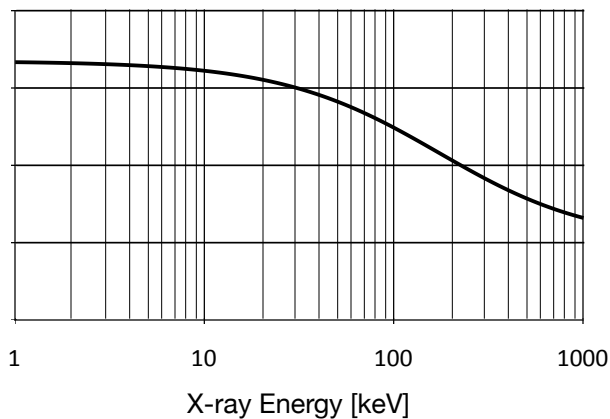
$$n \sim 4 - 5$$

$$Z \uparrow \Rightarrow \sigma \uparrow$$

Scattering

$$\sigma \sim Z \times$$

(curve)

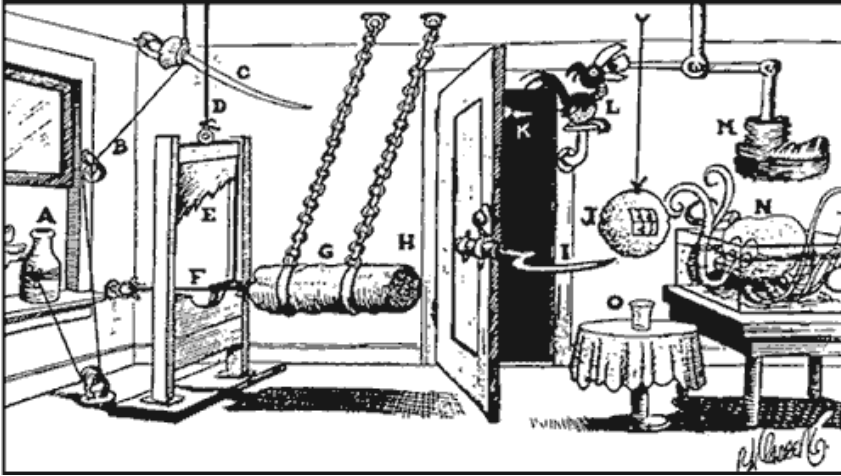


Scattering is elastic (e^- stays in ground state)
or Compton (e^- ejected)



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Quantum Efficiency (again)



- Probability of detecting incident photon
- Photon has to create ionization electron
- Ionization electron has to be detected



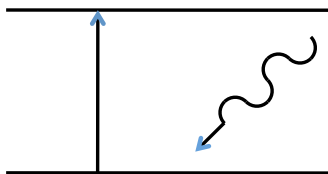
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What can the Ionization Electron Do?

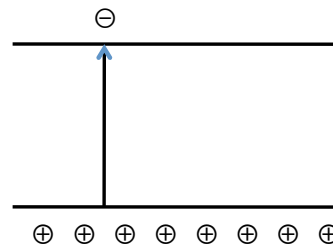
Form free charge



**Scintillation
(radiative)**

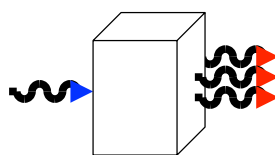
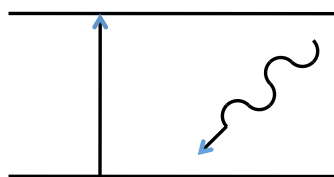


**Charge collection
in semiconductor**



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Scintillator



“Converts” x-ray (or other higher energy particle) into visible light

- Organic
- In-organic
- Mono-crystals
- Powders
- Liquids
- Plastics
- ...



$\rho, \tau, N_{\gamma}, \dots$

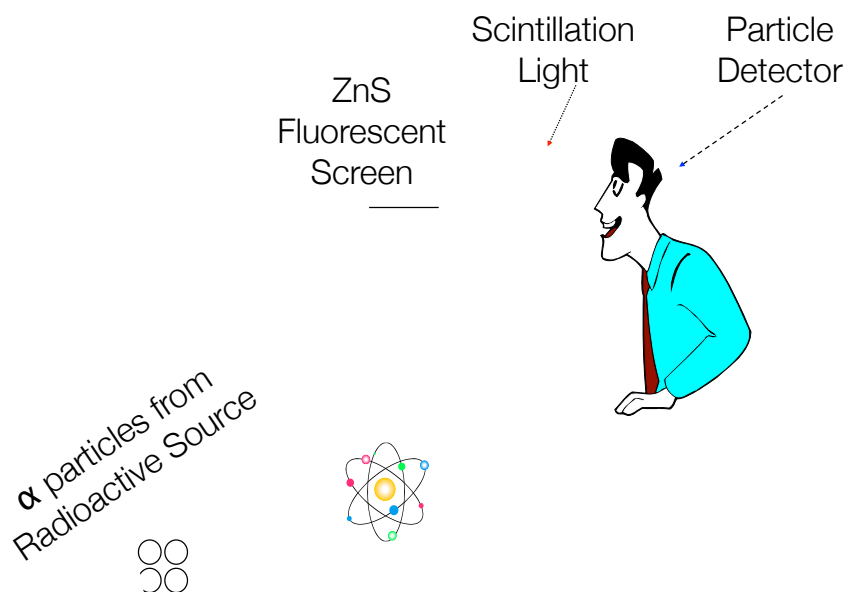
MATERIAL	DENSITY [g/cm ³]	EMISSION MAXIMUM [nm]	DECAY CONSTANT (1)	REFRACTIVE INDEX (2)	CONVERSION EFFICIENCY (3)	HYGROSCOPIC
NaI(Tl)	3.67	415	0.23 ms	1.85	100	yes
CsI(Tl)	4.51	550	0.6/3.4 ms	1.79	45	no
CsI(Na)	4.51	420	0.63 ms	1.84	85	slightly
CsI (undoped)	4.51	315	16 ns	1.95	4 - 6	no
CaF₂(Eu)	3.18	435	0.84 ms	1.47	50	no
⁶ LiI (Eu)	4.08	470	1.4 ms	1.96	35	yes
⁶ Li - glass	2.6	390 - 430	60 ns	1.56	4 - 6	no
CsF	4.64	390	3 - 5 ns	1.48	5 - 7	yes
BaF ₂	4.88	315	0.63 ms	1.50	16	no
		220	0.8 ns	1.54	5	
YAP (Ce)	5.55	350	27 ns	1.94	35 - 40	no
GSO (Ce)	6.71	440	30 - 60 ns	1.85	20 - 25	no
BGO	7.13	480	0.3 ms	2.15	15 - 20	no
CdWO₄	7.90	470 / 540	20 / 5 ms	2.3	25 - 30	no
Plastics	1.03	375 - 600	1 - 3 ms	1.58	25 - 30	no



For more, see <http://scintillator.lbl.gov/>

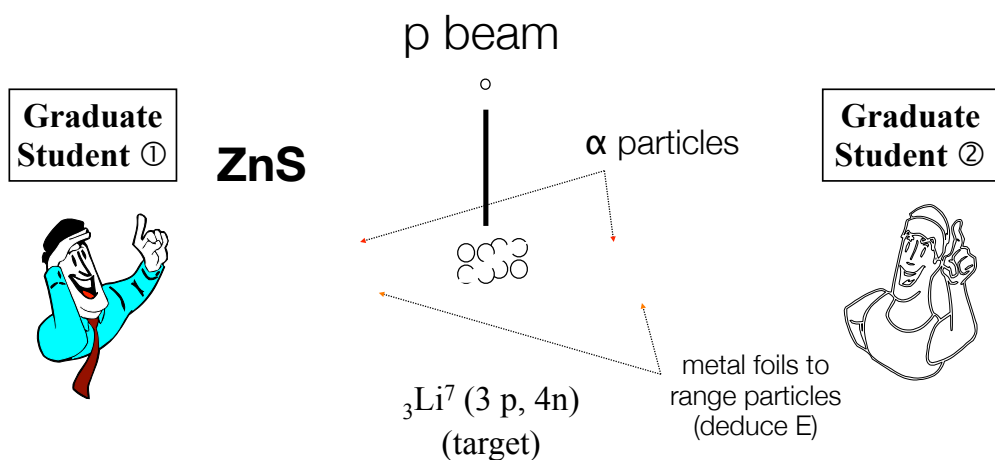
Visible Scintillation Counting

e.g. Rutherford 1911 - Discovery of the nucleus



Coincidence Experiment

Cockcroft+Walton, 1932

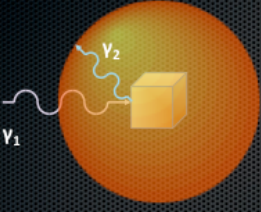


First demonstration that E (from $p + {}^3\text{Li}^7 \rightarrow \alpha + \alpha$) = Δmc^2
 (Δm is difference between initial and final nuclei masses)



Detector Properties

Ideal Detector



- ◆ Spatial information
 - ◆ $(x, y)_{\gamma_2}$
- ◆ Temporal information
 - ◆ $t(\gamma_2)$
- ◆ Energy information
 - ◆ E_{γ_2}
- ◆ With
 - ◆ High efficiency
 - ◆ $P_{\text{DETECT}}(\gamma_2) = 1$
 - ◆ 4π solid angle
 - ◆ **low cost**

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2 x 0D detectors

Coincidence technique

~Hz data rate

E via attenuation



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Advantages and Disadvantages

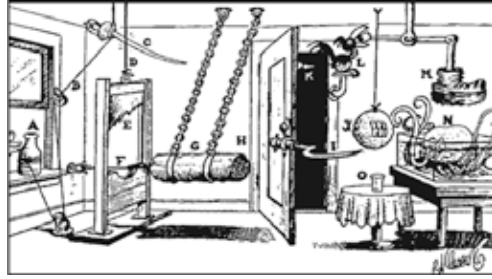
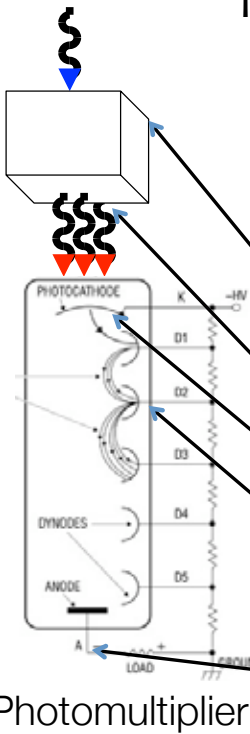
- Low Power (graduate students don't need much food)
- Low Speed - counting rate limitations ~ 1 Hz
- Threshold sensitivity
 - (although Marsden could distinguish α and p by brightness)
 - At $\lambda \sim 500$ nm, $\text{Threshold}_{\text{TRAINED OBSERVERS}} \sim 17 \gamma$ for $t_{\text{FLASH}} > 40 \mu\text{s}$
- Yield: *"...at one famous laboratory during this period all intending research students were tested in the dark room for their ability to count scintillations accurately. Only those whose eyesight measured up to the standards required were accepted for nuclear research; the others were advised to take up alternative, less exacting, fields of study"*



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From Birks

Typical Scintillation Detector



- Incident photon creates (ionizing) photo-electron
- Ionization generates visible photons
- Visible photons converted into electrons
- Electrons “amplified” by secondary emission
- Output current detected

Photomultiplier

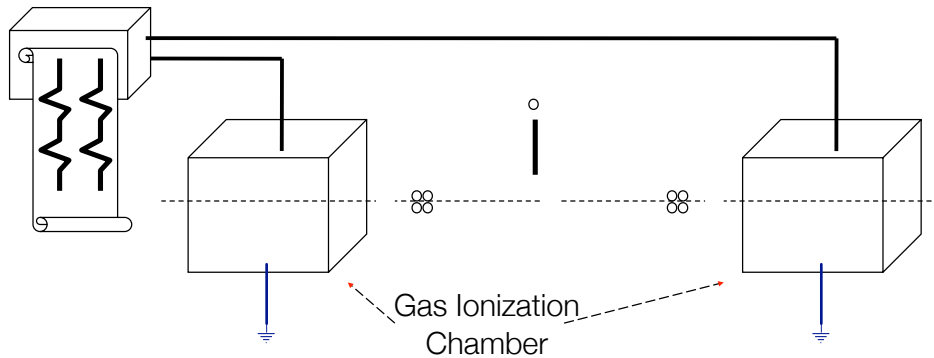


Coincidence Experiment

Cockcroft+Walton - Electronic Verification

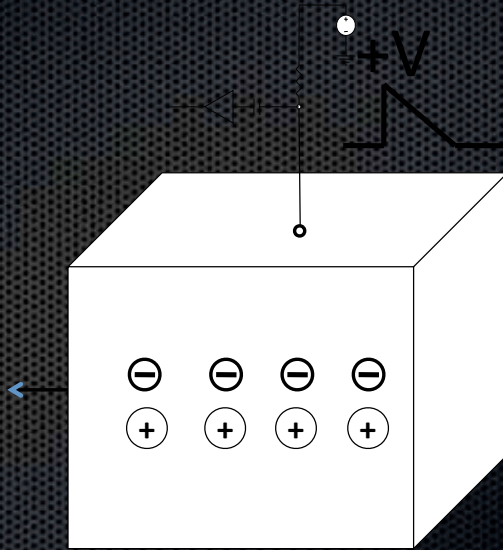
One of the last visual counting experiments
(and one of the first electronic counting experiments)

Oscillograph

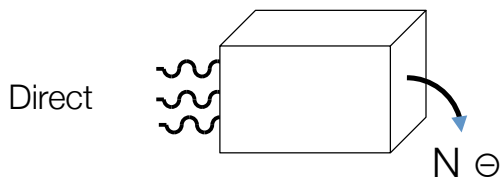


Ionization Chamber

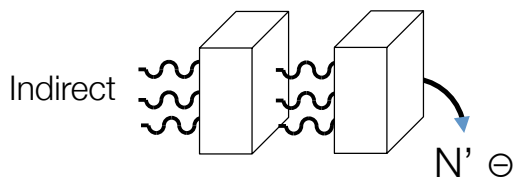
- Particle passes through chamber and creates an ionization track
 - Image charge Q_i appears on positively charged plate
- Electrons move (with speed = drift velocity) towards positively charged plate
 - As the electrons arrive, they reduce the charge on the plate
- A current pulse has been created at the same time the particle has passed through the chamber



Electronic Detectors



Incident radiation converted into N charges inside "Sensor"



Incident radiation converted into some other form of radiation, which in turn is converted into N' charges inside "Sensor"

*Historical terms
Semi-meaningless*



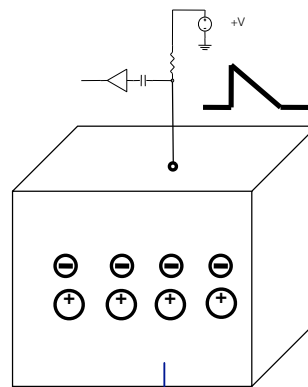
Energy Needed for Detection

"Sensor"	$\eta = E$ per secondary quanta	Mechanism
Gas	30 eV	e ⁻ /ion pairs
Scintillator	10 – 1000 eV	optical excitation
Semiconductor	1 – 5 eV	e ⁻ /hole pairs
Superconductor	~meV	breakup of Cooper pairs
Superconducting calorimeters	~meV	phonons



Statistics – Fano Factor

"Sensor"	$\eta = E$ per secondary quanta	Mechanism
Gas	30 eV	e ⁻ /ion pairs
Scintillator	10 – 1000 eV	optical excitation
Semiconductor	1 – 5 eV	e ⁻ /hole pairs
Superconductor	~meV	breakup of Cooper pairs
Superconducting calorimeters	~meV	phonons



$$N_{\pm} = \frac{E}{\eta}$$

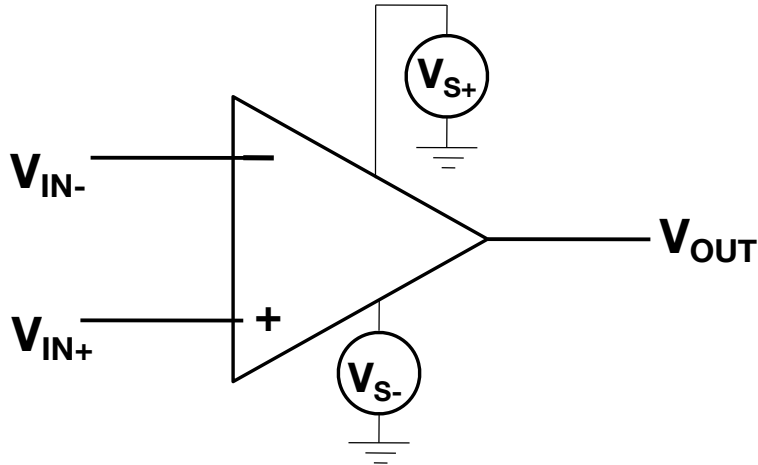
$$\sigma_N = \sqrt{FN}$$

- Intrinsic resolution is Fano-limited
- $\sigma_N/N \downarrow$ as $\eta \downarrow$
- Hence interest in superconducting calorimeters
- There are additional ways to have fluctuations on N



Next Problem – the current pulse is usually very small

It must be amplified

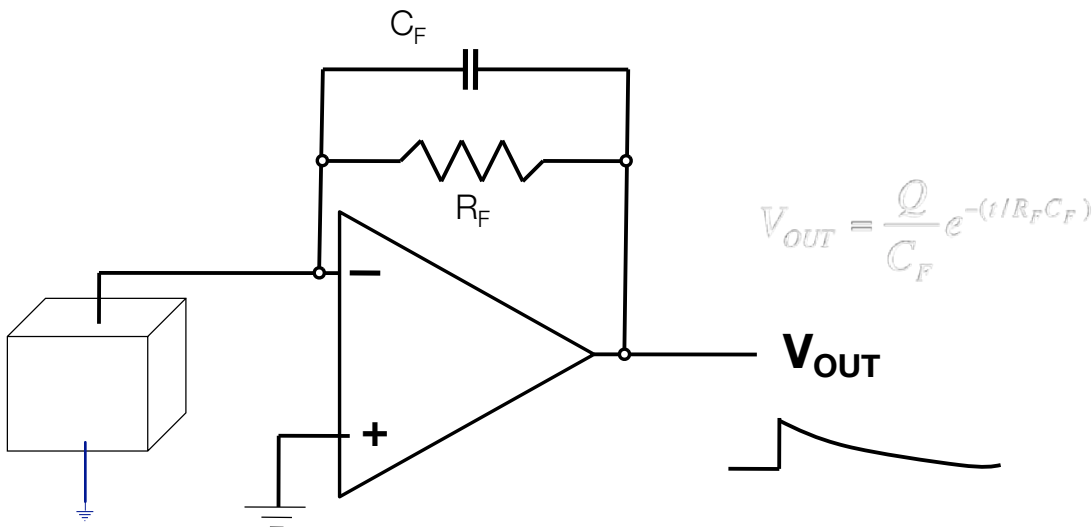


$$V_{OUT} = \begin{cases} V_{S+} & \text{if } V_{IN+} > V_{IN-} \\ V_{S-} & \text{if } V_{IN+} < V_{IN-} \end{cases}$$



Let's take this further (70 years of electronics in 3 seconds)

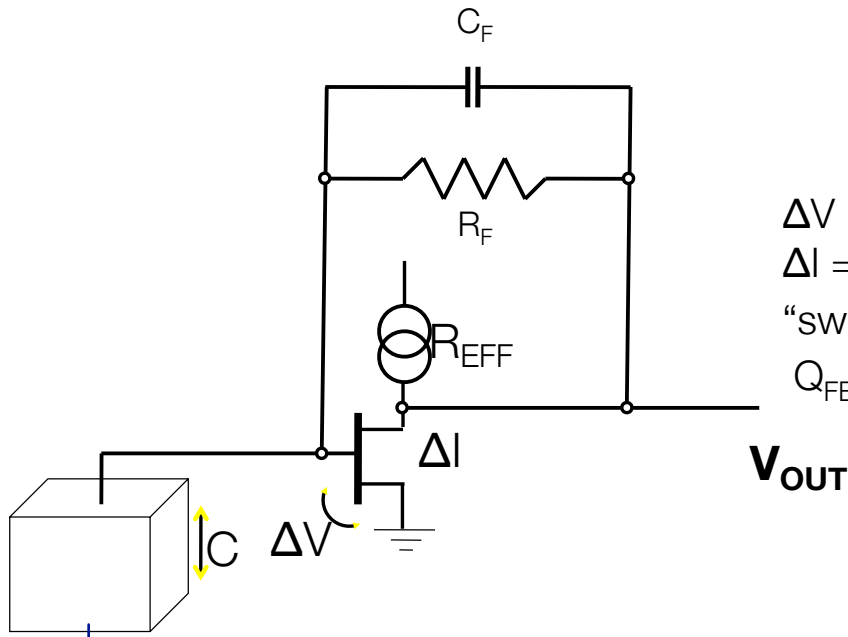
Charge-sensitive pre-amplifier



Charge appears all at once (δ function)



Almost Always Like This



$$\Delta V = Q/C$$

$$\Delta I = g_m \cdot \Delta V$$

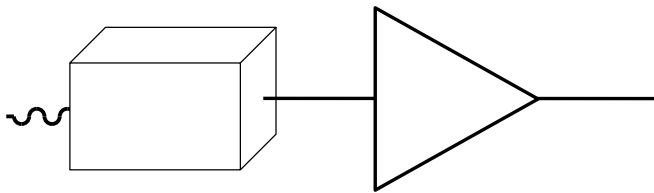
$$\text{"swing"} = \Delta I \cdot R_{EFF}$$

$$Q_{FB} = Q = C_F \cdot V_{OUT}$$



Noise and Statistics

Some terms to get started



● Incident photon creates electron of energy E_γ (photoelectric) or $< E_\gamma$ (Compton) (with probability "QE")

● Electron creates **on average** $N = E_e/\eta$ e/h pairs

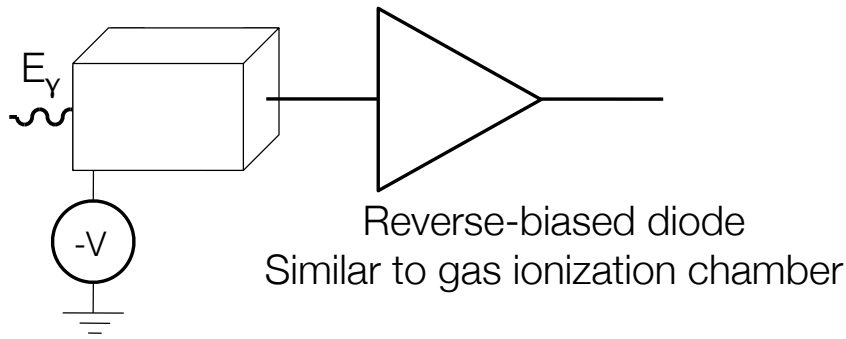
● Output pulse height = Gain x N Volts

● Output electronic noise V_N Volts



Semiconductor Detector

p-i-n diode



Reverse-biased diode
Similar to gas ionization chamber

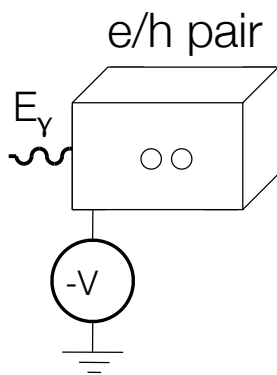
$$N = E_\gamma / \epsilon$$

$$\sigma_N^2 = F \cdot E_\gamma / \epsilon, \quad F = \text{Fano factor}$$

Material	Si	Ge	GaAs	Diamond
η [eV]	3.6	3.0	4.4	13.1
F	0.12	0.13	0.10	0.08
ρ [g/cm ³]	2.3	5.3	5.3	3.5



How it Works

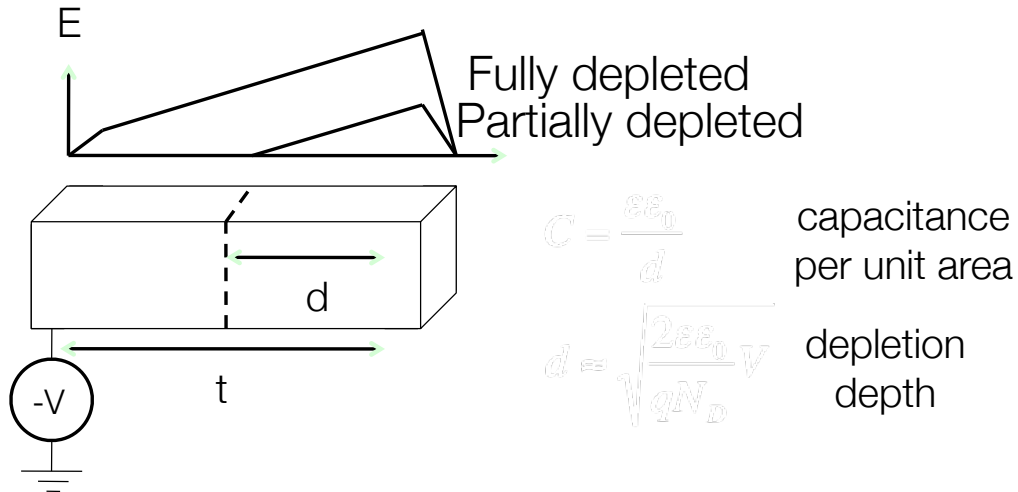


- Recombination
 - e⁻ recombination time $\propto 1 / \text{hole concentration}$
- Diffusion
 - In field-free region, e⁻ diffuses (into 4π)
 - $D = (kT/q)\mu$ ($\mu = \text{mobility}$)
- Drift
 - In non-zero field region e⁻ moves towards positive plate with velocity $\mu \cdot E$

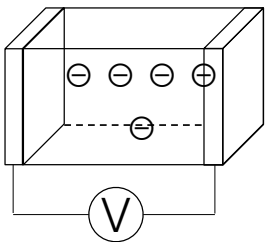


Depletion

Fully depleted → minimize diffusion (and recombination)

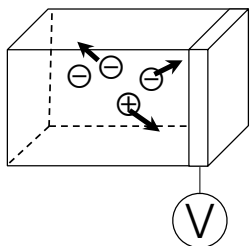


Importance of Depletion



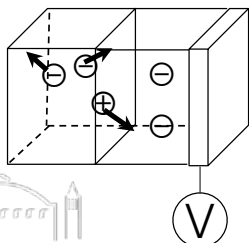
◆ Fully depleted detector

No recombination – collect all charge (spectroscopic)
 Charge drifts to collection electrode
 PSF = 0 (best spatial resolution)



◆ Undepleted detector

Diffusion + recombination
 Poorer PSF
 Poorer spectroscopic capability



◆ Partially depleted detector

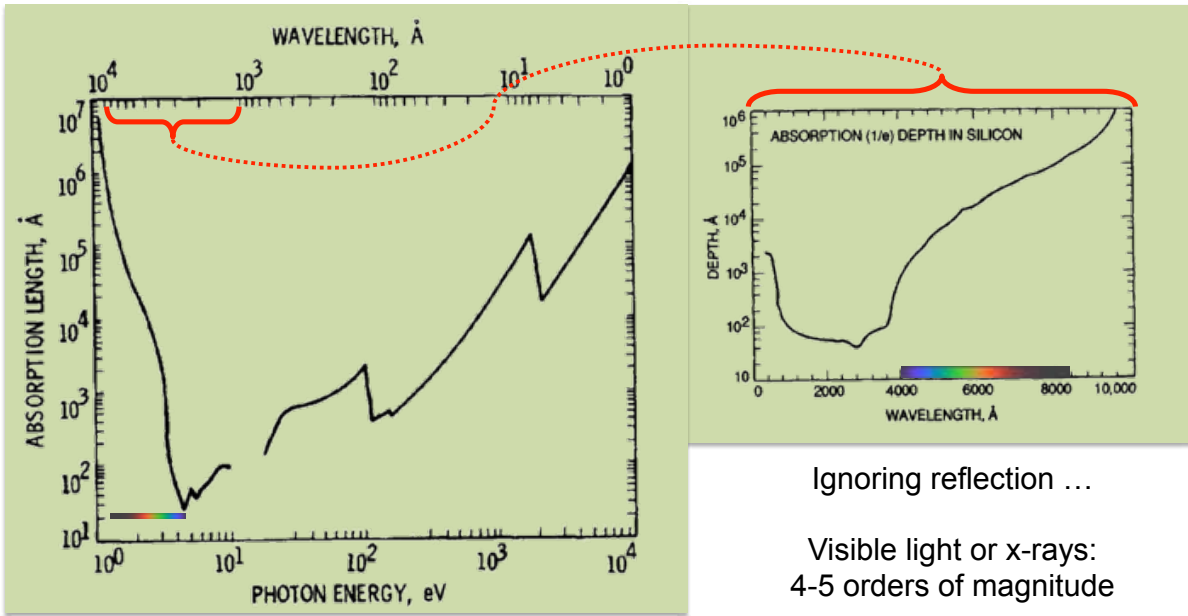
PSF and charge collection depend on site of photoconversion

Charge collection

- ▶ drift - all charge drifts directly towards anode
- ▶ diffusion - charge goes into 4π
- ▶ recombination - no charge collected



Absorption in Si



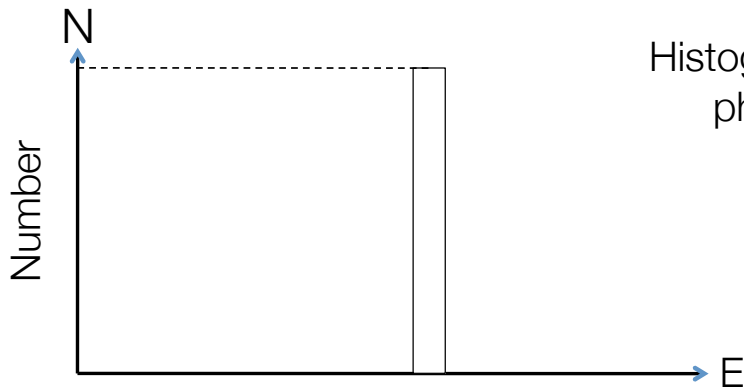
Ignoring reflection ...

Visible light or x-rays:
4-5 orders of magnitude

Bandgap of Si at 300K = 1.1 eV
pure Si transparent for $\lambda > 1.1 \mu\text{m}$

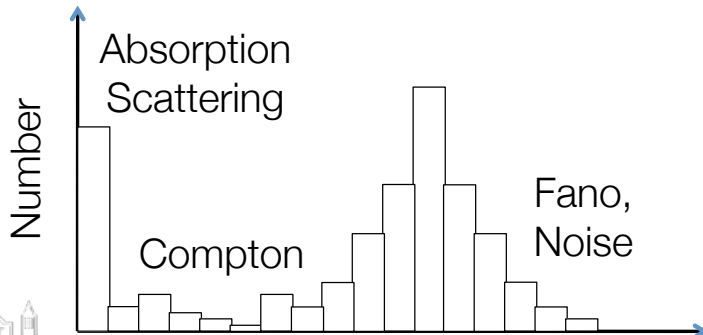


Send N X-rays (of Energy E) Into Detector



Histograms of detected
photon energies
 $\Sigma = N$

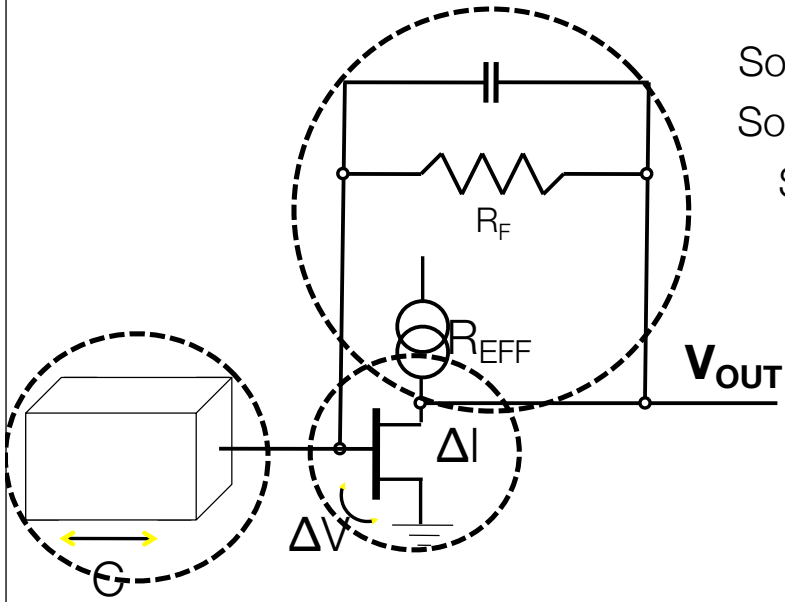
Desired



Measured



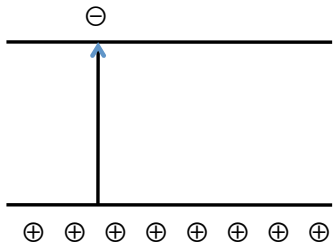
Noise



Source #1 – “input stage”
 Source #2 – the detector
 Source #3 – everything else



The Detector Makes Noise?



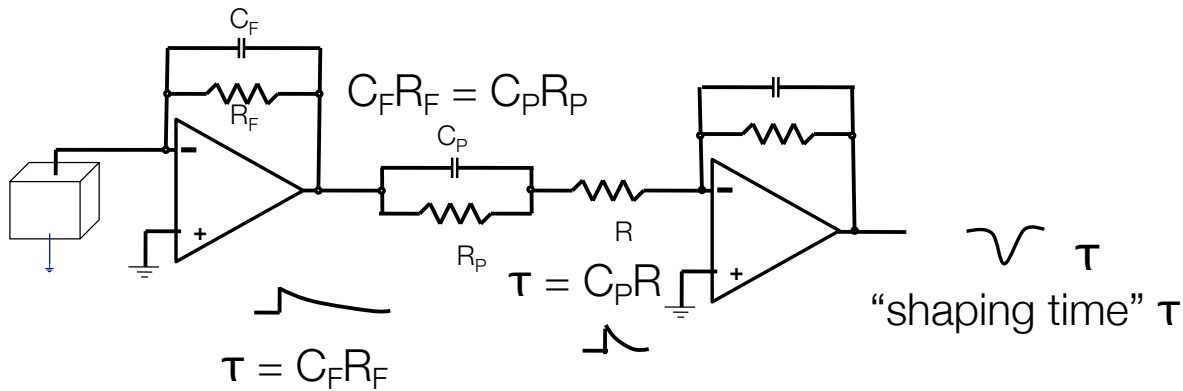
Semiconductor detector
 i.e. valence band ~full,
 conduction band ~empty

eV band gaps → **thermal excitation** of carriers

- Thermal excitation
 - “leakage” or “dark” current ($I_{LEAK} e^-/s$)
 - “looks like” signal
 - (“shot noise”)
 - Reduced by cooling
- Noise, $\propto \sqrt{I_{LEAK}}$, because leakage is not orderly

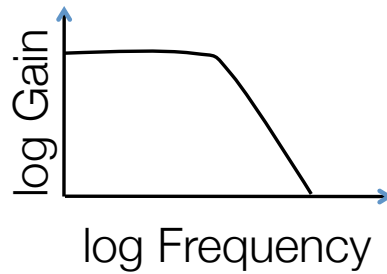


Some More Electronics



Bandwidth = $1 / 2\pi \tau$

In frequency domain:

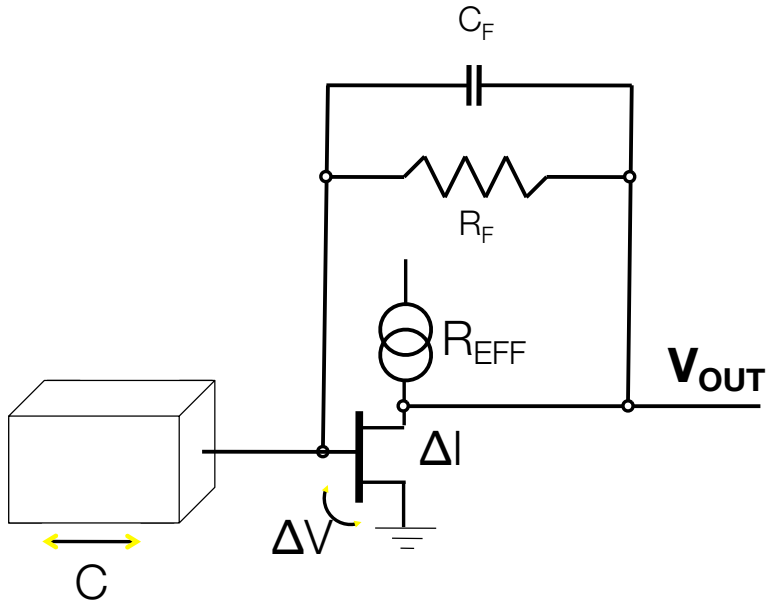


Things $\propto \tau$

- Double pulse resolution $\Delta t \propto \tau$
- Noise due to leakage current \propto
 - \sqrt{I} – random arrival of leakage charge
 - $I \sim e^{-T}/T^2$
 - $\sqrt{\tau}$ – i.e. $\sqrt{[e^-/s] \cdot [s]}$
- Longer integration time (τ) increases noise due to leakage current
- Must want **short** integration time

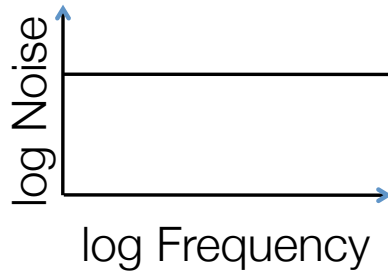


Electronic Noise

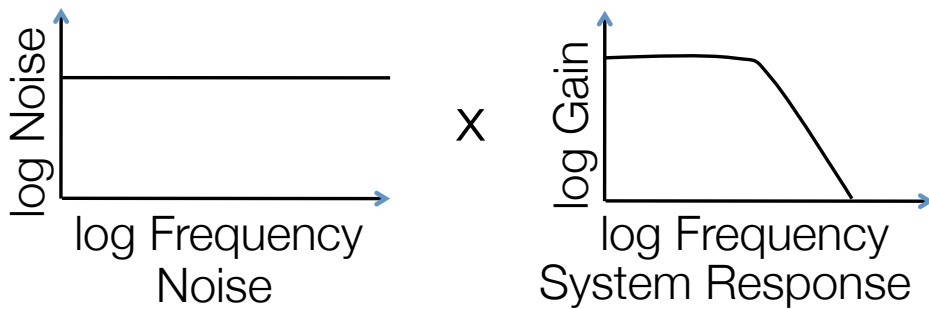


Resistors make noise
(Thermal excitation of carriers in resistor means $I \times R = V_{\text{NOISE}}$.)

Thermal noise is truly random, $V_N \sim \sqrt{4kTR}$



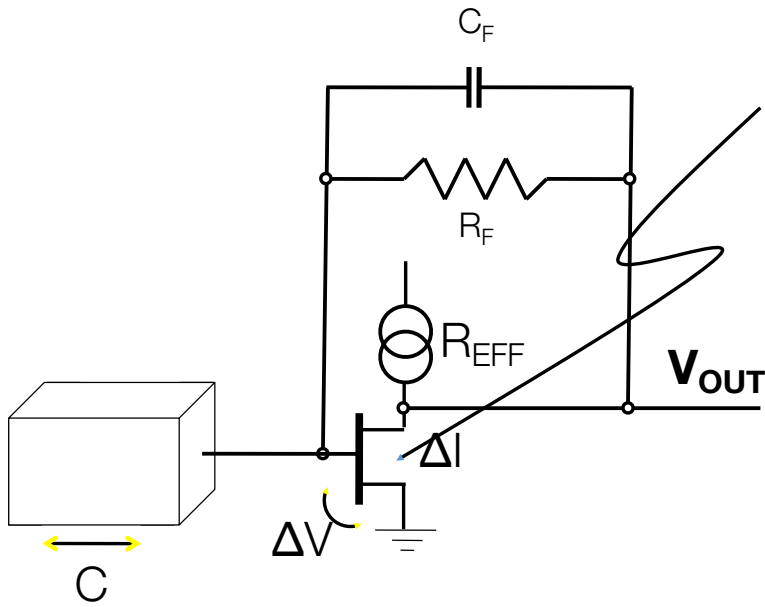
Contribution of Thermal Noise



- Noise is frequency independent
- So response is $\propto \sqrt{\text{Bandwidth}}$
- Must want **long** integration time



It's Worse



Thermal noise $\sqrt{(4kT/g_m)}$

→ δV_{OUT} (from noise)

Input stage will "compensate"

Noise "charge" at input

$$\delta Q = C_F \delta V_{OUT}$$

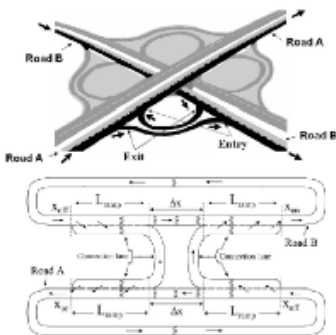
$$\Delta V \text{ (at input)} = \delta Q / C$$

Noise $\propto C$



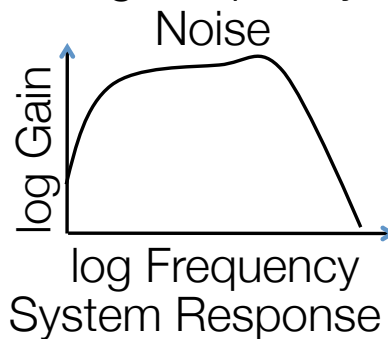
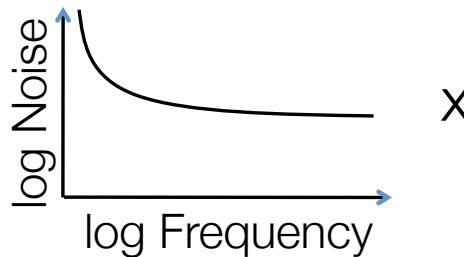
It's Even Worse

Many physical systems are subject to fluctuations $\sim 1/f^\alpha$
You know this from driving:



RMS of time you wait getting onto the freeway $\sim 1/f$

Same with electronics. So there is an optimum



Not so Simple

1. Fluctuations in number of photons “absorbed”
 2. Fluctuations in number of secondary particles created
 3. (Fluctuations in number of tertiary particles created)
 4. Electronic noise
- **Energy** resolution: 2, 3 and 4
 - Quantum efficiency: 1 (but maybe 2, 3 and 4)



Detective Quantum Efficiency

- Combine notion of Quantum Efficiency (probability of detecting a particle) with spatial response (probability of detecting/quantifying $N(x,y)$ particles) \rightarrow DQE
- How faithfully does the detector transfer the (spatially varying) fluctuations of the input signal
- $DQE(\omega_x, \omega_y)$

- Many definitions – most common is $DQE = \frac{(S/N)_{OUT}^2}{(S/N)_{IN}^2}$

- Example, flat field illumination (flux ϕ) of detector with certain QE

$$(S/N)_{IN} = \frac{\phi A \tau}{\sqrt{\phi A \tau}} \quad (\text{Poisson})$$

$$(S/N)_{OUT} = \frac{QE \times \phi A \tau}{\sqrt{QE \times \phi A \tau + \sigma_N^2}}$$

for electronic noise σ_N



S/N, Dynamic Range, Number of Bits

Usually mis-stated!

● Si: $\eta = 3.6$ eV. Inject 3.6 keV γ s (generates on average 1,000 e/h pairs) and measure the output pulse height \rightarrow “conversion gain” = Volts / $e^- = V_e$

● RMS noise at output = V_N

● ENC (Equivalent Noise Charge) = V_N/V_e

● If the maximum voltage that the system can measure is V_{MAX} , then the dynamic range is V_{MAX} / V_N

● Example: $V_e = 1 \mu\text{V} / e^-$, $V_N = 100 \mu\text{V}$

● ENC = $100 e^- = 360$ eV [RMS]

● $V_{MAX} = 1\text{V} \rightarrow \text{DR} = 1\text{V} / 100 \mu\text{V} = 10^4$

● $N_{BITS} = \ln(\text{DR}) / \ln(2)$

● $\ln(10^4) / \ln(2) = 13$ bits (i.e. $2^{13} \approx 10^4$)

● S/N has specific meanings, that are not any of these!



A tale of 3 different \sqrt{N}

● Uniform flux ϕ [$\gamma/\text{cm}^2/\text{s}$] on area A yields $N = \phi A$ [γ/s] $\pm \sqrt{N}$ incident photons/s

● photostatistics

● Each one (that is converted) produces $N_{\pm} = NE/\eta \pm \sqrt{(FN_{\pm})}$ e/h pairs/s

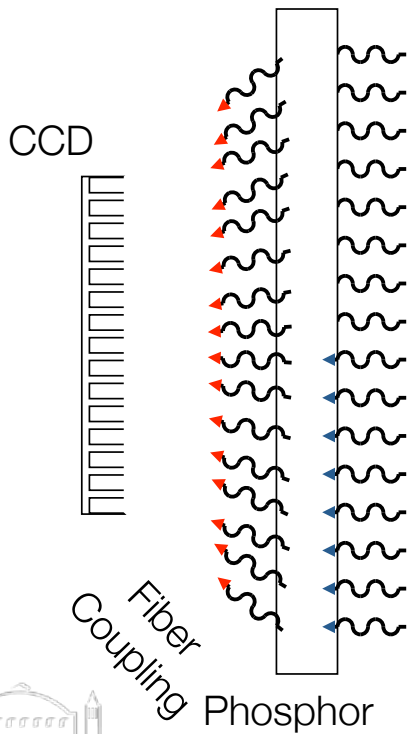
● intrinsic resolution

● Which, as a current sampled in time τ has fluctuations $\sim \sqrt{(N_{\pm}\tau)}$

● shot noise



“Classical” X-ray Detector



- Phosphor (powdered scintillator)
- Fiber-optically coupled to a CCD (2D solid-state detector) camera
- + and –
 - “general purpose”
 - radiation damage
 - area
 - phosphor
 - fiber-optic

Scientific CCDs (Charge-Coupled Devices)



Dumbbell nebula - LBNL CCD

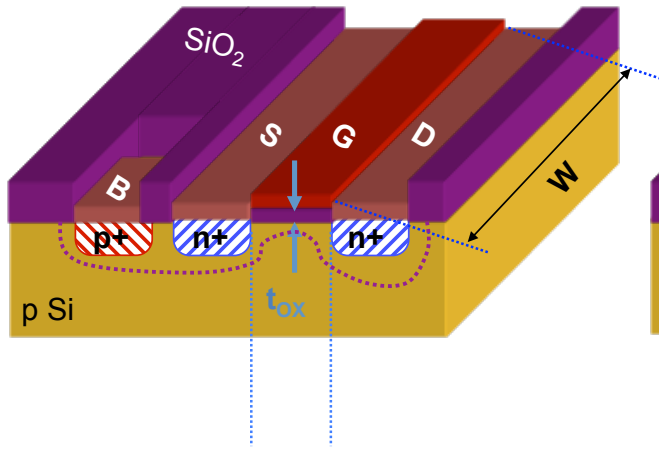
Blue: H- α at 656 nm
 Green: SIII at 955 nm
 Red: 1.02 μ m

- CCD invented in 1969 by Boyle and Smith (Bell Labs) as alternative to magnetic bubble memory storage
- LST (“Large Space Telescope” – later Hubble) 1965 – how to image?
 - Film was obvious choice, but - It would “cloud” due to radiation damage in space Changing the film in the camera not so trivial
 - 1972 CCD proposed

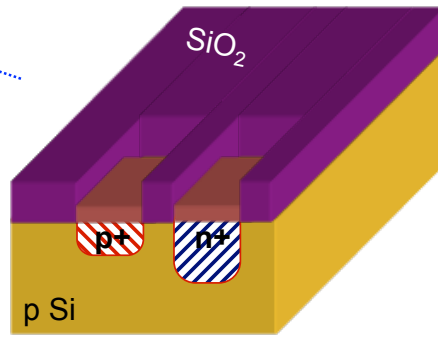
2009 Nobel Prize in Physics



Si Processing: Integrated Circuit Elements



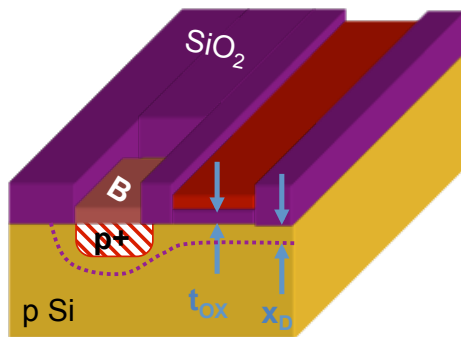
MOS Transistor



pn Diode



Integrated Circuit Elements

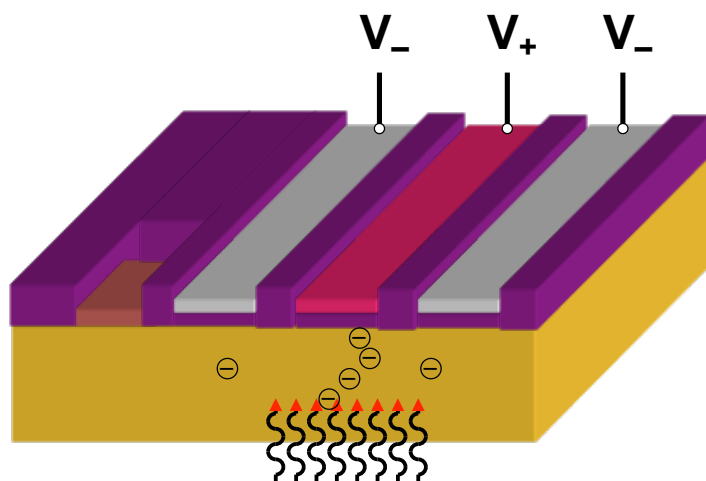


$$C = \frac{1}{\frac{1}{C_{OX}} + \frac{1}{C_{DEP}}}, \quad C_{OX} = \frac{\epsilon_{SiO_2}}{t_{OX}}, \quad C_{DEP} = \frac{\epsilon_{Si}}{x_D}$$

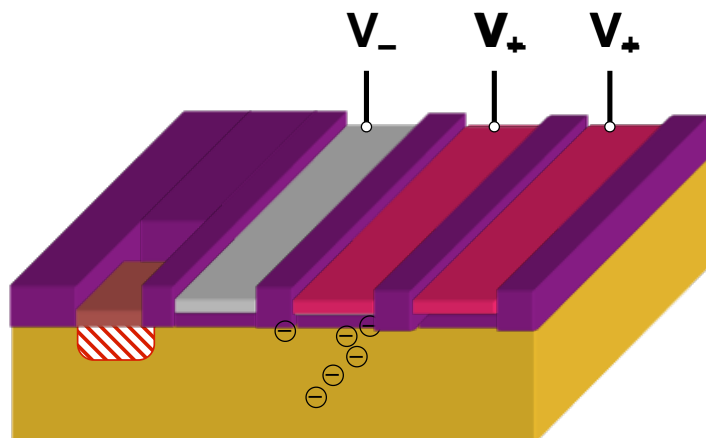
MOS Capacitor



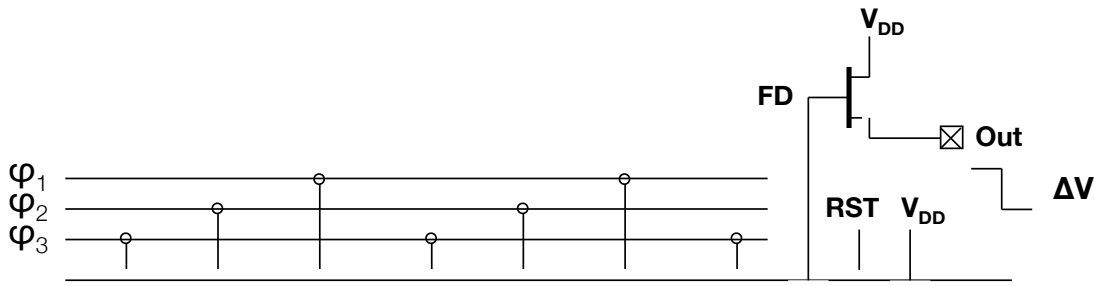
Accumulate Charge



Accumulate and Transfer Charge



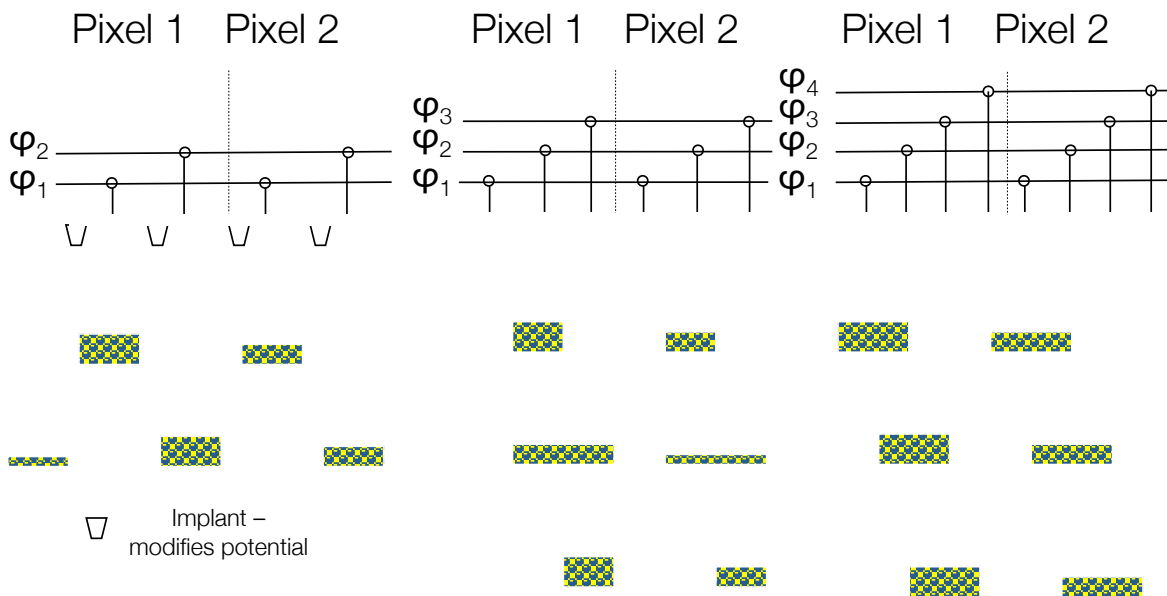
Conventional 3-Phase CCD



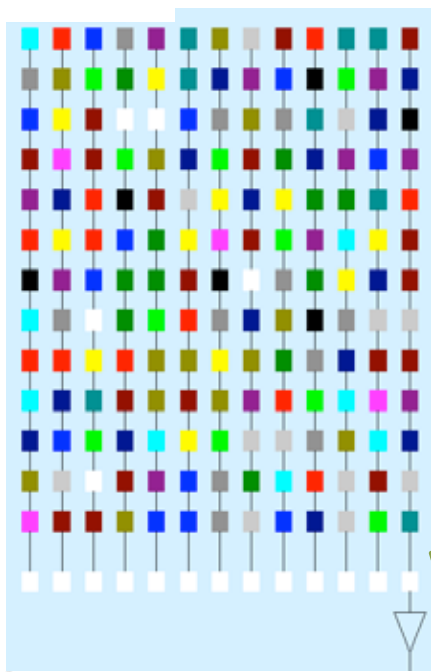
- Noiseless, ~lossless charge transfer
- High gain charge-to-voltage conversion $\Delta V = q/C_{FD}$
- Output amplifier (source follower, or ...) on-chip



Many ways to do this



How it Works

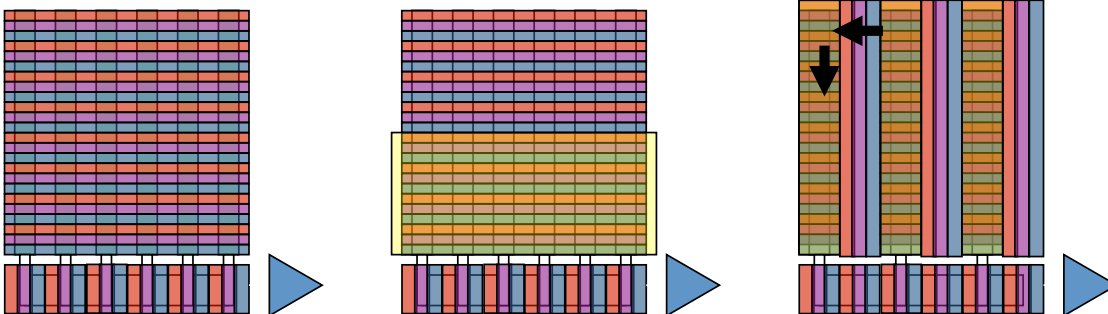


- Image area – $N_x \times N_y$ pixels
- Output shift register (N_x pixels)
- Expose image area
- Shift one row into output shift register
- Shift out each pixel
- Repeat



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Several architectures



Full frame

Frame transfer

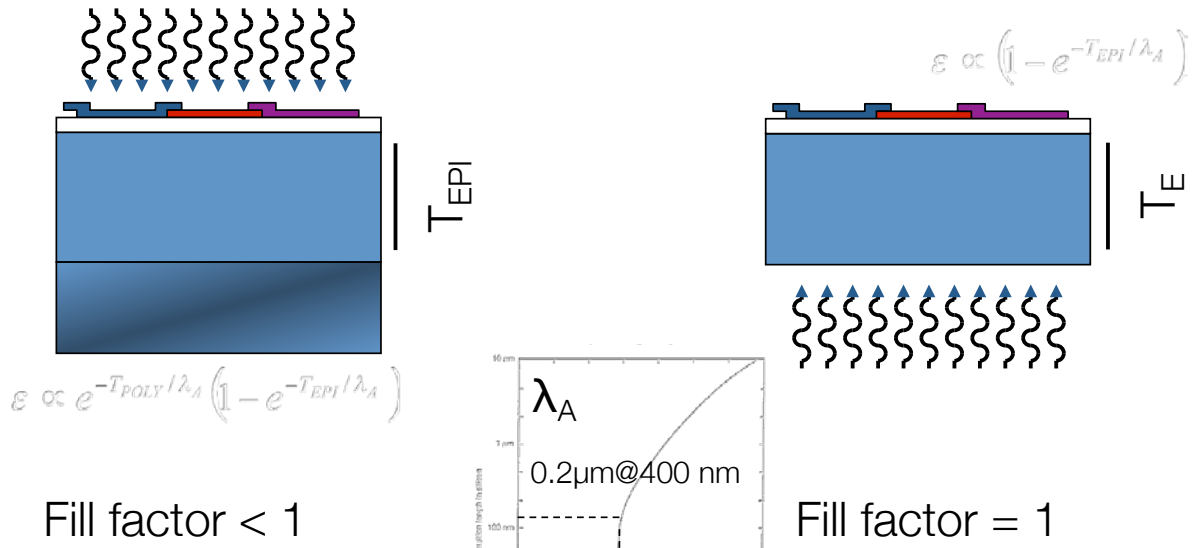
Interline

Rapid shift from image to storage
Slower readout of storage during integration



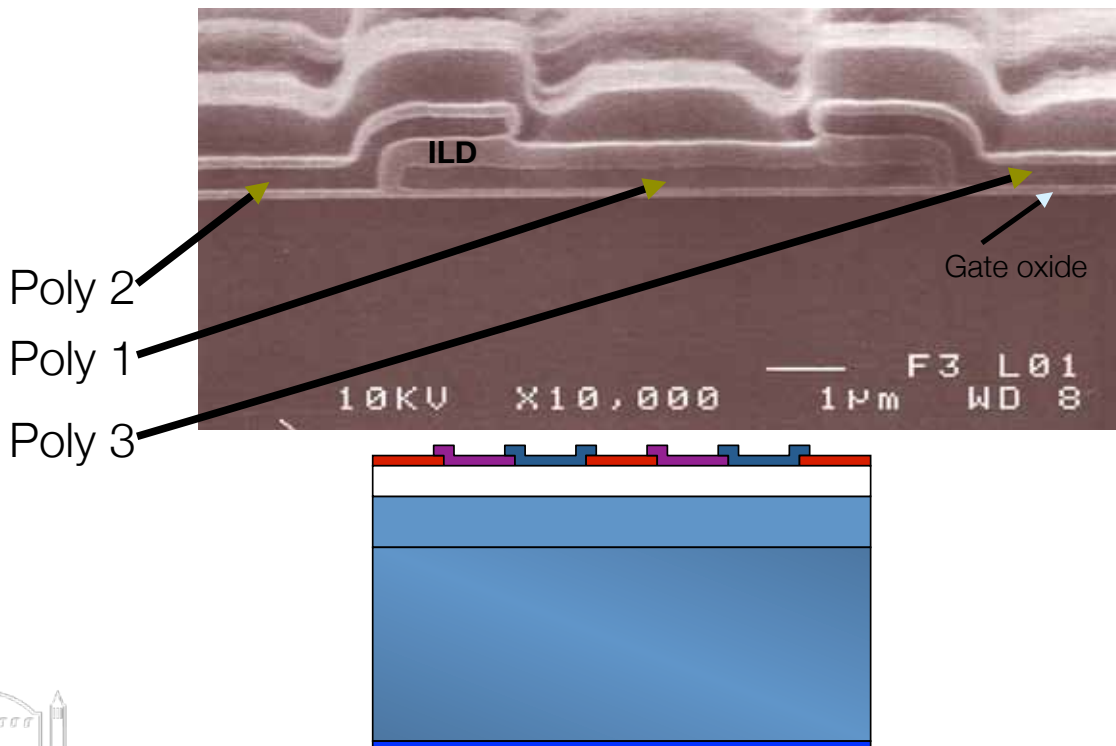
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Frontside/Backside Illumination



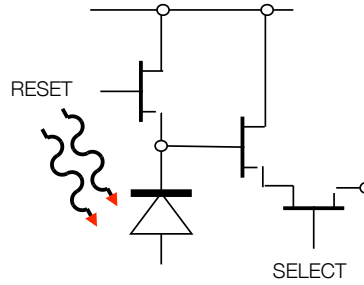
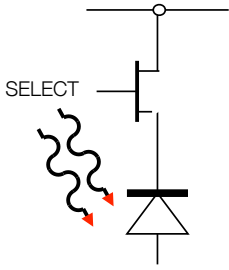
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Triple Poly CCD Process



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Monolithic Image Sensors



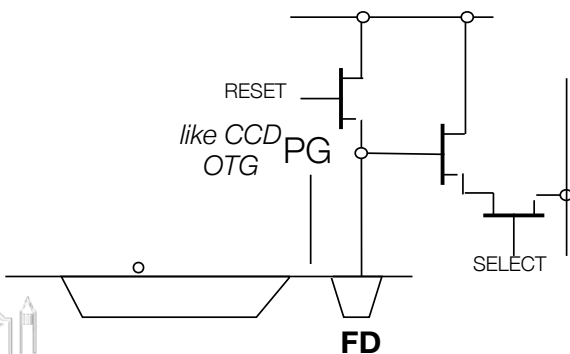
- Passive Pixel Sensor
- Proposed 1968
- No Reset, no in=pixel amplifier

- Active Pixel Sensor
- Also proposed 1968
- Many ways to make the photodiode



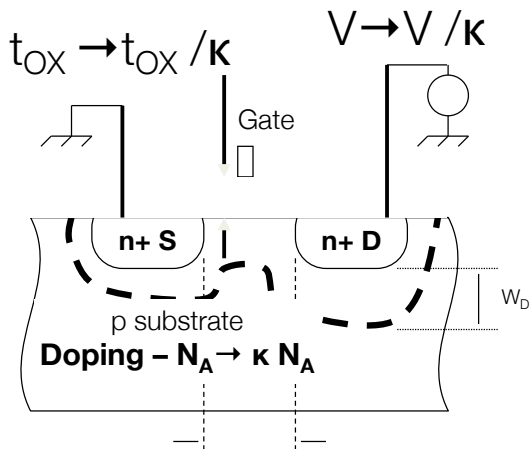
CCD vs APS

- APS – transfers a *voltage* down the column
- CCD – (noiselessly) transfers a *charge* down the column
- APS – can be more sensitive (source follower does not have to drive off-chip)
- APS – fill factor < 1 in general
- Photogate APS – like a matrix of individual CCDs
- Backside illumination – attempted for APS, work-in-progress



CMOS, CMOS “opto” and CCD processes

CMOS driven by constant field scaling



	CCD	CMOS
t_{ox} (Å)	500 - 1000	5-20
Well depth (μm)	2.5	0.5 deeper for RF
Implant (μm)	~ 1 channel stop	0.1 S/D implants
V	≥ 10	<3.3 <2.5 <1.x ...
Poly layers	3 (2)	1 2 for analog
Subst. quality	Low leakage	Don't care Except opto

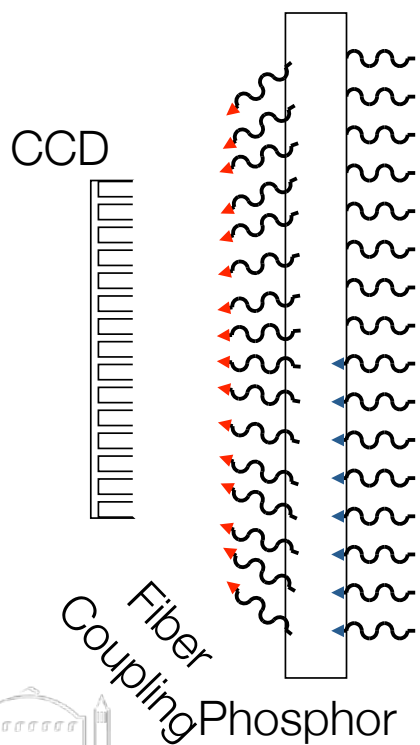


Why CCDs?

- Low noise (noiseless charge transfer, do everything to make C_{FD} small in order to get large conversion gain)
- Fill-factor = 1 (for backside illumination)
- Linear and easy to calibrate
- **Long history of scientific use**
- Large area devices easier (cheaper) to develop as CCDs than as state of the art CMOS devices
 - Readily wafer scale
- Commercially produced



“Classical” X-ray Detector

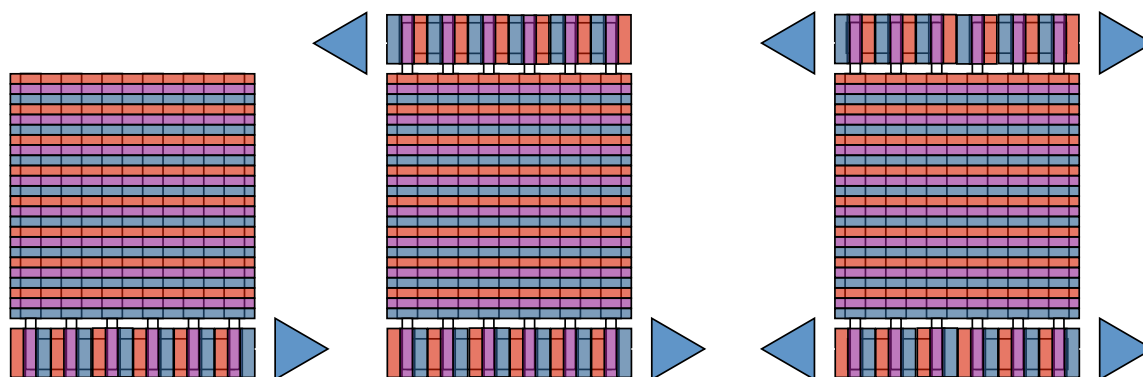


- Phosphor (powdered scintillator)
- Fiber-optically coupled to a CCD (2D solid-state detector) camera
- + and –
 - “general purpose”
 - radiation damage
 - area
 - phosphor
 - fiber-optic



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CCDs are Wonderful, but SLOW



Now it gets more difficult



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Increase ADC speed

$$T_f = \frac{N_V}{2} \left(T_V + \frac{1}{B_V} \left[B_H T_H + \frac{N_H}{B_H N_{port}} T_{CONV} \right] \right)$$

top+bottom readout

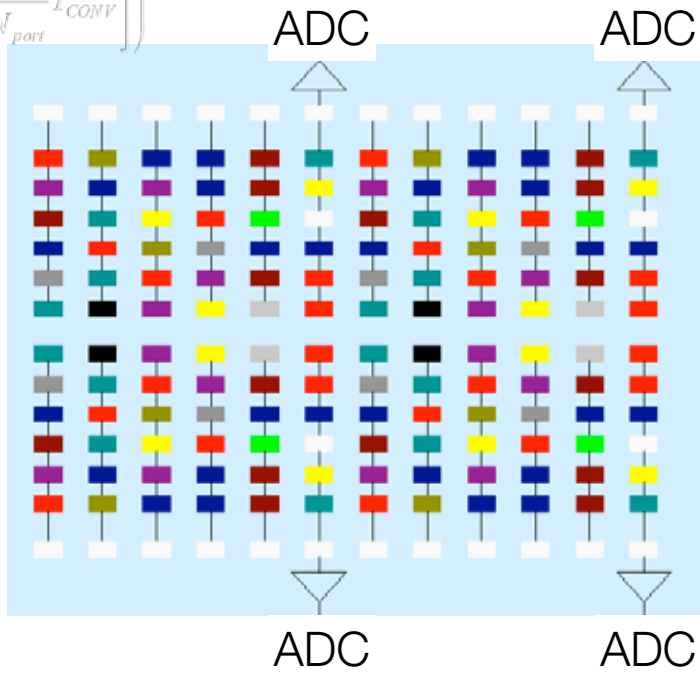
$N_V, N_H = \# H, V$ pixels

$B_V, B_H = H, V$ binning

$T_V, T_H = H, V$ shift time

$N_{port} = \#$ ports

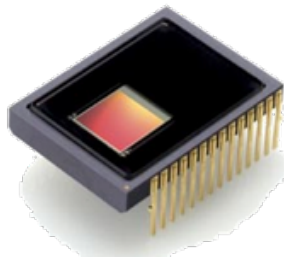
$T_{CONV} =$ total conversion time including reset, summing well, ...



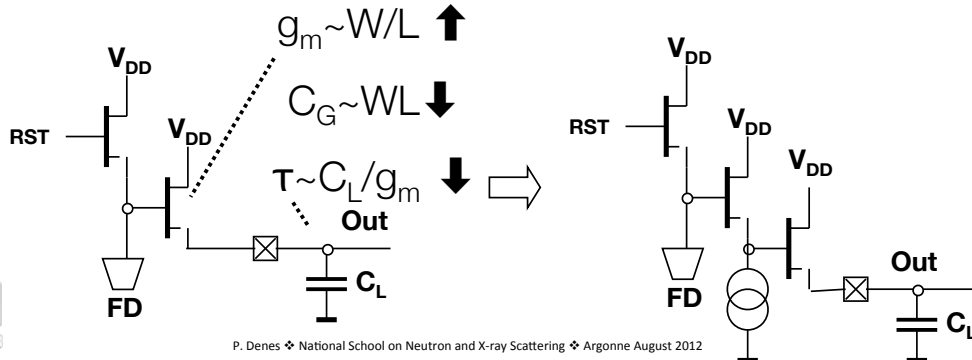
For example

Increase readout/ADC speed

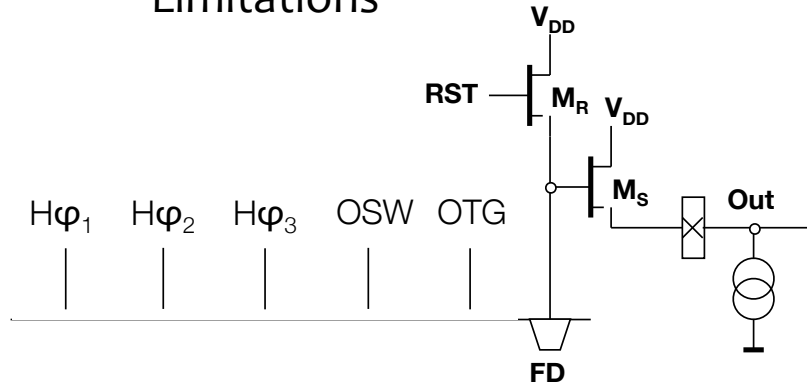
- Dalsa – FT50M
- 1024 x 1024 x 5.6 μm pixel
- Frame transfer / 2 ports
- 100 fps = 100 MPix/s
- 11.1 bits [67 dB] at 30/60 fps
- 10.1 bits [61 dB] at 50/100 fps



S/F Limitations



Limitations



● \sqrt{kT} Noise contribution from M_R (reset switch) removed by CDS (correlated double sampling – measure V_R and $V_R + V_S$)

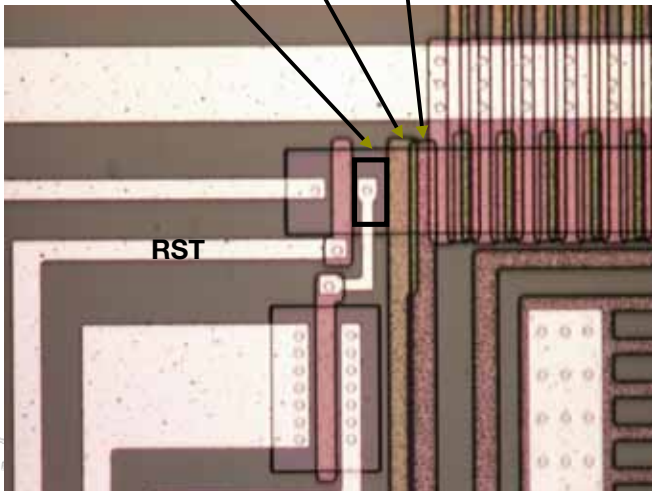
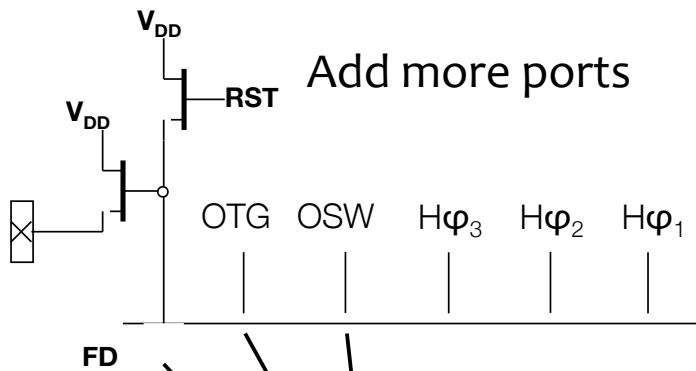
● Noise contributions from M_S (source follower)

● Thermal noise $V_n^2 \sim 4kT\gamma g_m \int H^2(f) df$

● 1/f noise $V_n^2 \sim \frac{K}{C_{ox}WL} \int H^2(f) \frac{1}{f} df$

● Noise from current source

↑ $\sim \sqrt{\text{rate}}$



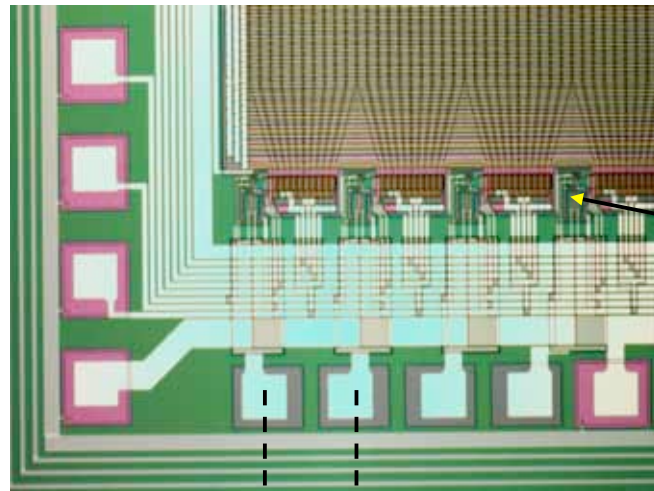
● Reset and output transistors need room

● Want to minimize C_{FD}

● Need space for the output stage!



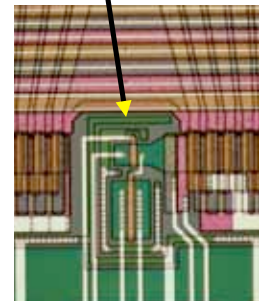
(almost) Column-Parallel CCD



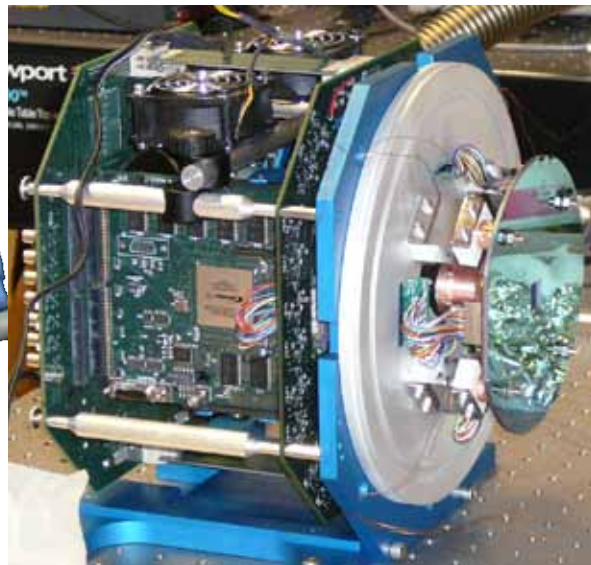
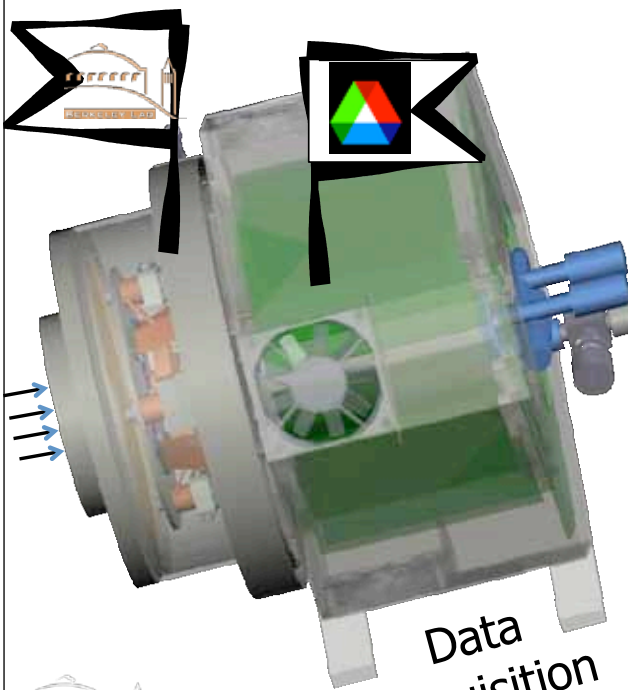
Mini-SR with taper
Metal strapping

Constant Area
Taper
Mini-shift reg.
Output stage

~300 μm pitch
bond pads
(wire-bondable)



ALS / APS Collaboration



Direct Detection

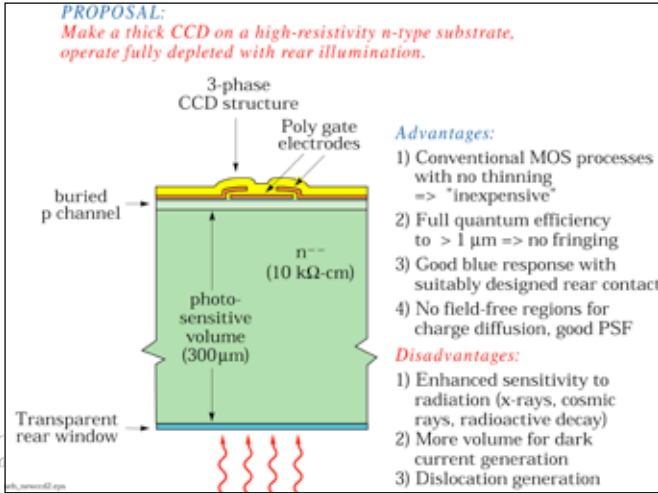
Previous example of CCD usage was for optical photons. What about x-rays?



T
t

This should be depleted – generally thin with conventional processes

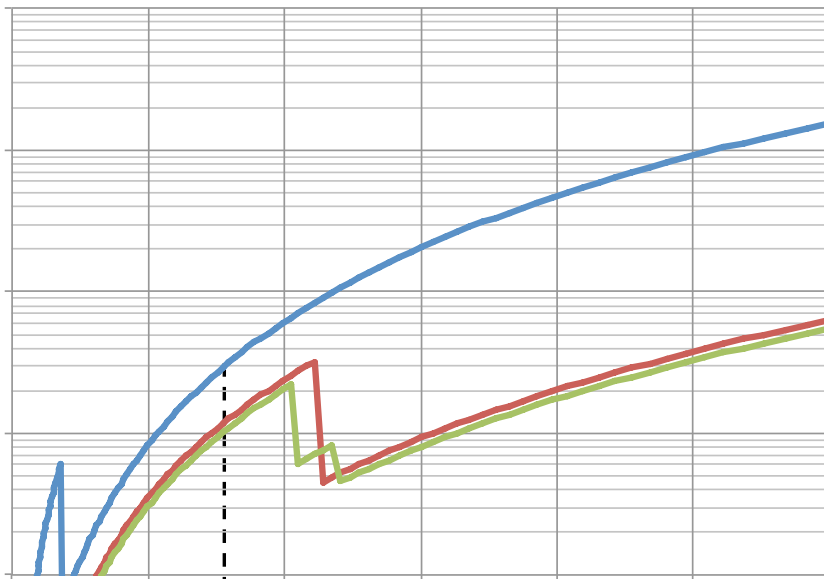
→ add a layer which can be used as an electrode



LBL CCD – S. Holland et al.



Detector Thickness to Collect 99% of Photons



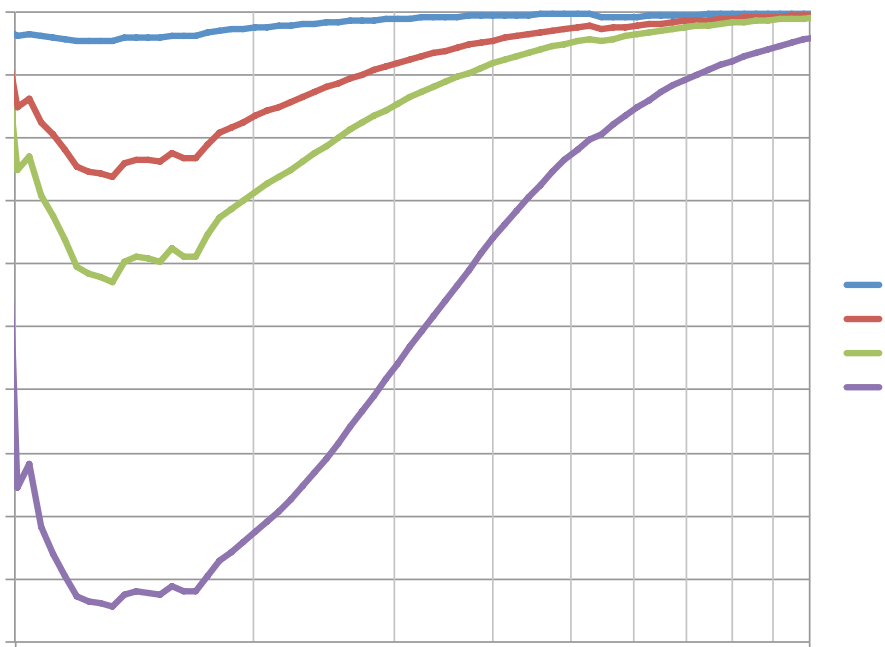
(T)



Hard X-ray challenges →

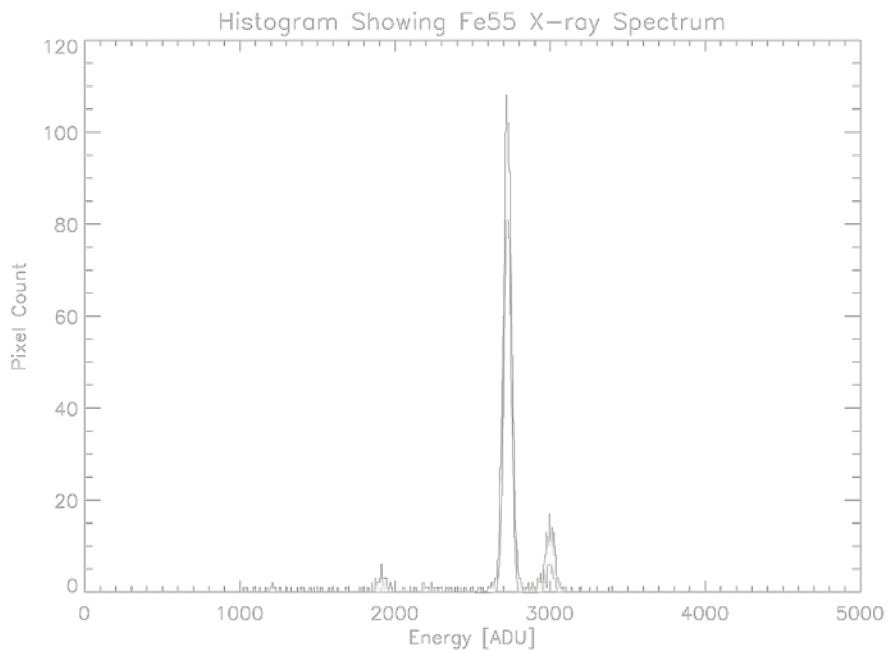


Thin “window” for Soft X-rays



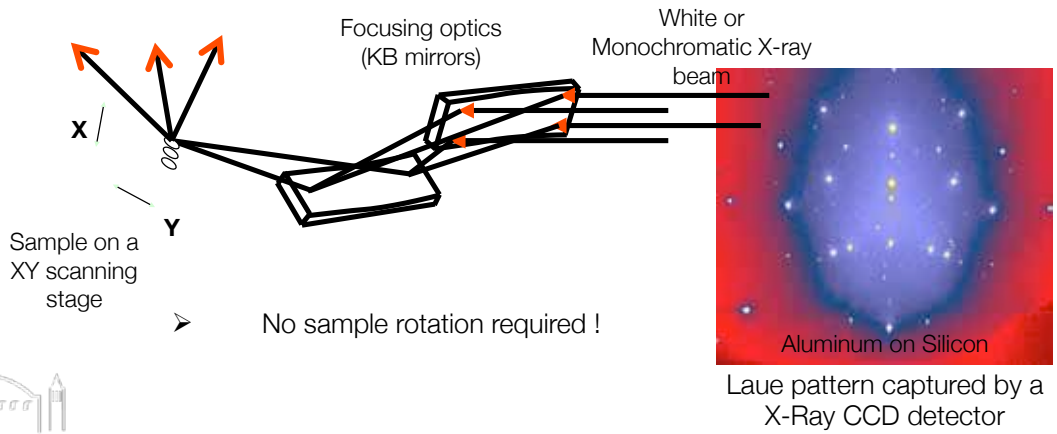
650 μm thick CCD

^{55}Fe K_{α} and K_{β} . Resolution ~ 126 eV at 5.6 keV

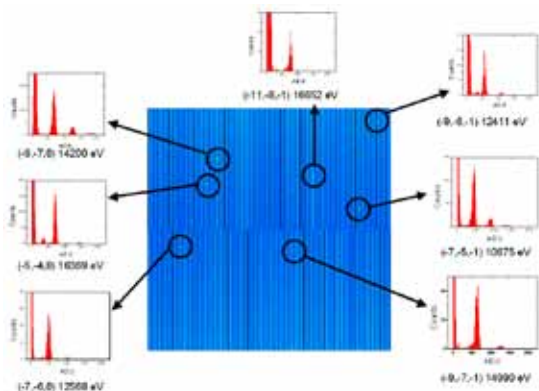


Example: X-Ray microdiffraction at the ALS

- Sample is raster-scanned under a submicron-sized white (or monochromatic) X-ray beam focused by Kirkpatrick-Baez mirrors. At each step a diffraction pattern is recorded.
- Analysis of the diffraction pattern scans provides with phase distribution, crystal orientation maps, strain/stress maps, dislocation structure and distribution
- The technique helps understanding the complexity of the micromechanics of materials (strength, resistance to failure, ...) at granular and subgranular level



Microdiffraction



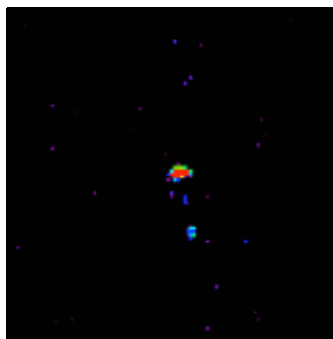
hours → seconds



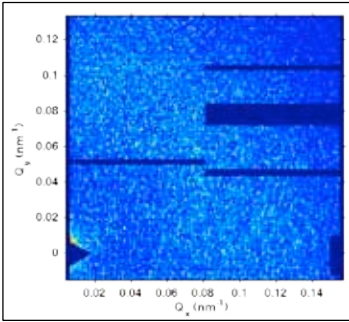
KTP crystal indexed. The energy of each reflection can be measured ...

⇒ Laue ab-initio indexation (of unknown structures, heterogeneous samples, ...)

⇒ Energy-resolved Laue diffraction for structure solution using Laue (pb of harmonics, scaling, ...)

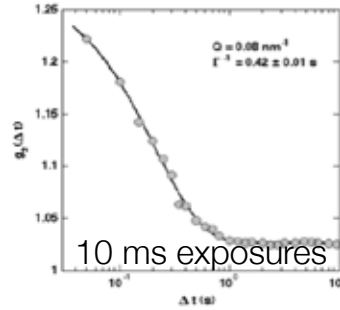
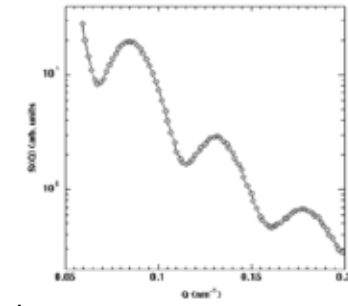
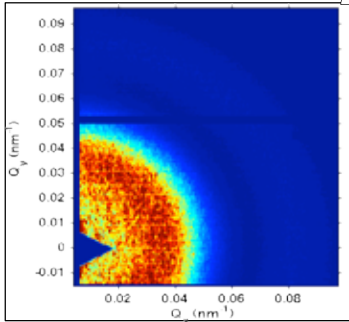


Example: XPCS at APS BL 8-ID



time autocorrelation

FastCCD at 8-ID



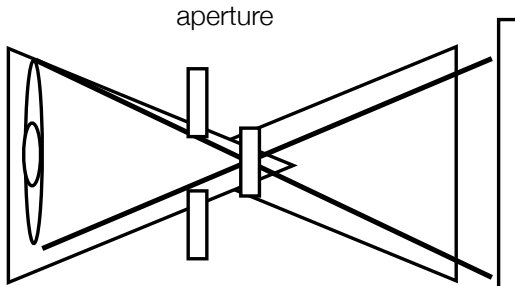
time average

XPCS Example – 71nm radius latex spheres in glycerol at ~-20 deg C
 (Data courtesy of Suresh Narayanan and Alec Sandy)

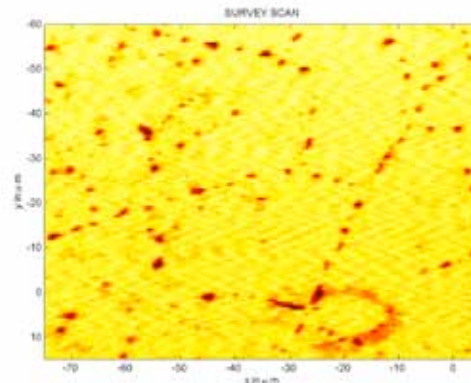
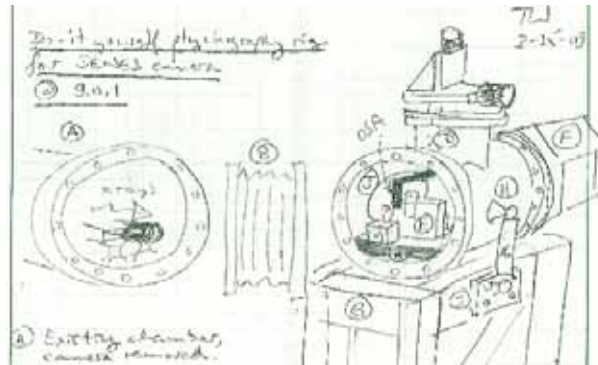
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Example: Coherent Imaging at ALS BL 9.0.1



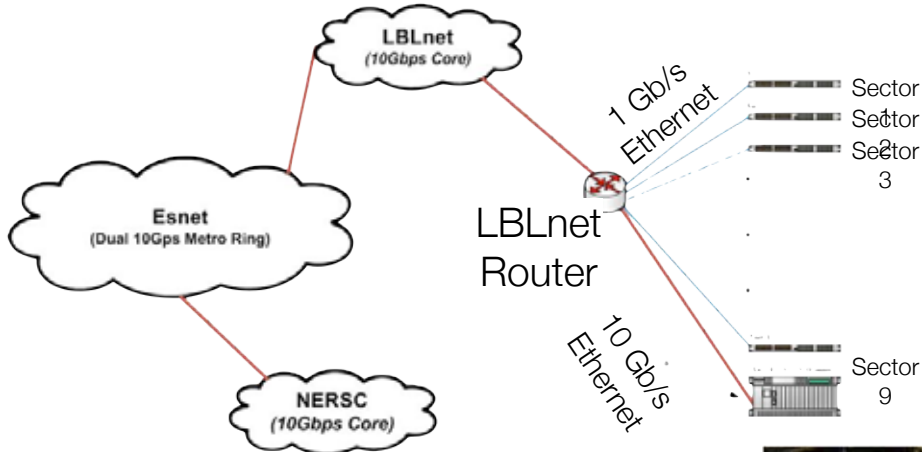
10 nm should be possible in near future



Soft X-ray Ptychography

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Fast Readout = Lots of Data



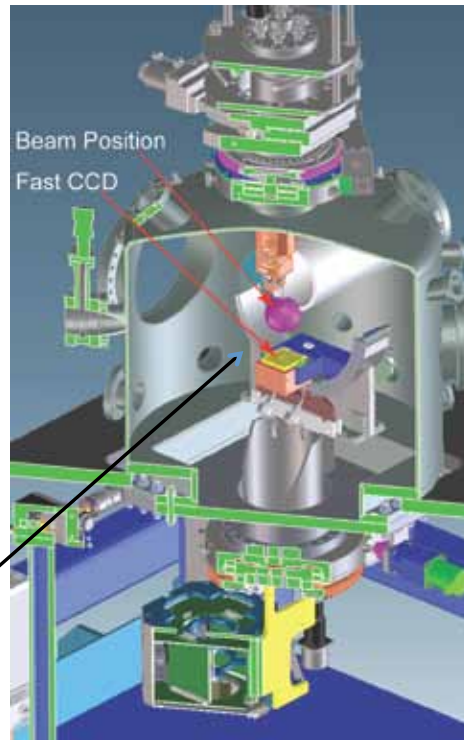
Phase 1 - ATCA to LBLnet
 Phase 2 - Install multiport
 10 Gb/s switch at Sector 9

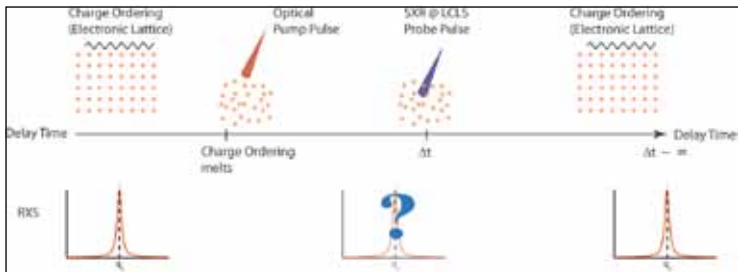


RSXS End Station for LCLS Hutch 2

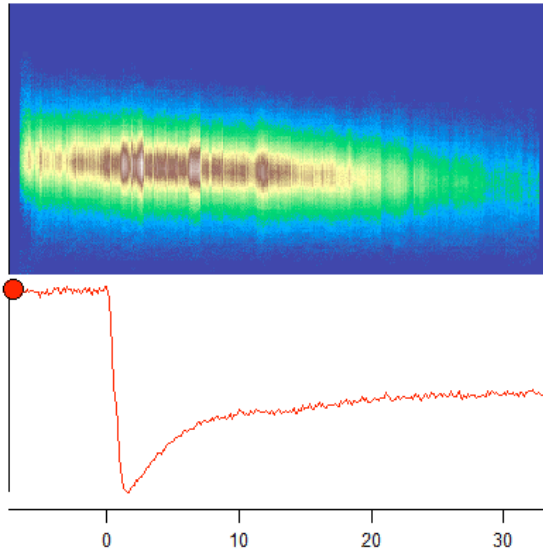


Goniometer
 360° horiz.
 100° vert.



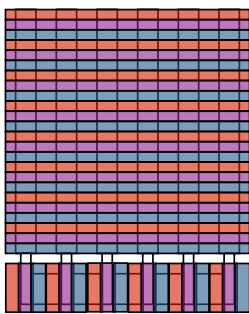


Fast melting and slow recovery of spin ordering around 50K (correct time jittering and intensity fluctuation)

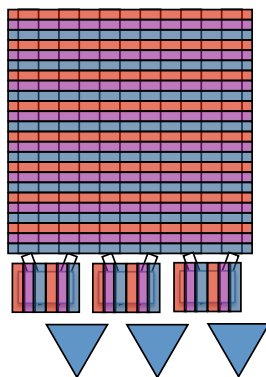


CCD → fCCD → vfCCD

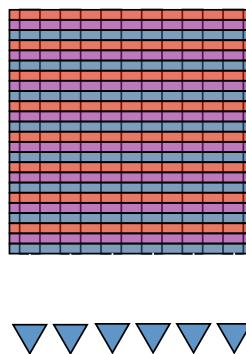
Conventional CCD
10⁰ Hz



(a)CP-CCD
10² Hz



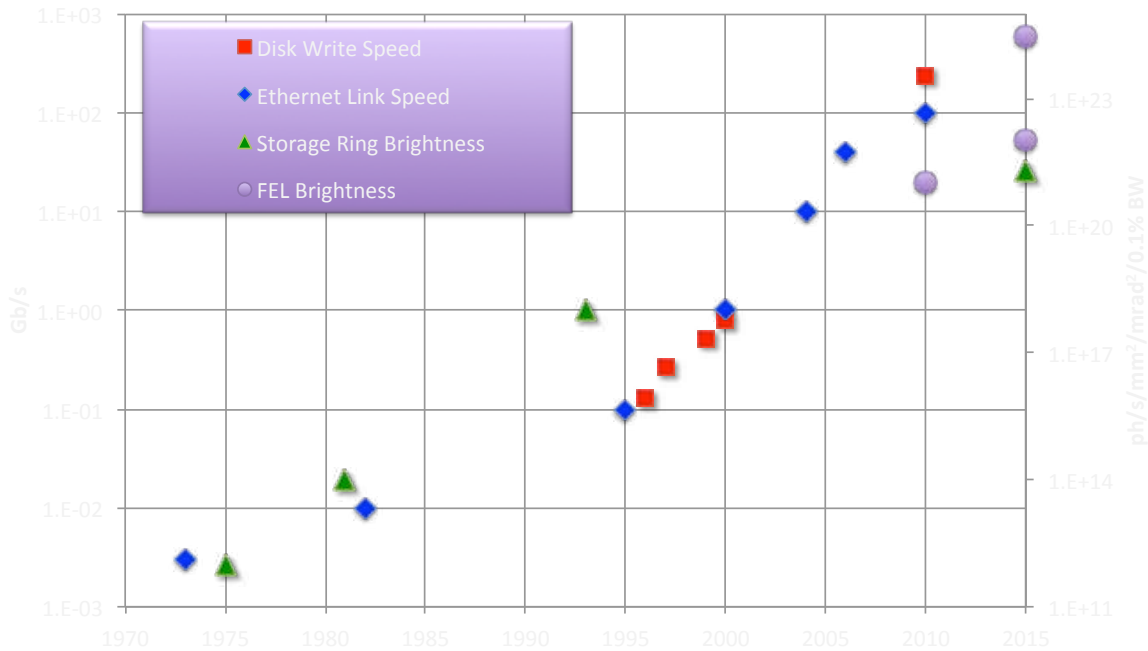
CP-CCD
10³⁻⁴ Hz



Conventional CCD	FastCCD	Very FastCCD
4-port	(almost)Column Parallel	Column Parallel
Commercial readout	fCRIC (custom 0.25 μm CMOS readout IC)	HIPPO (custom 65 nm CMOS readout IC)



Data Acquisition, Transmission and Processing



Future developments in processing

Low IQ detector



10² Hz



Clever detector



10^{3.5} Hz



Brilliant detector



10⁵ Hz

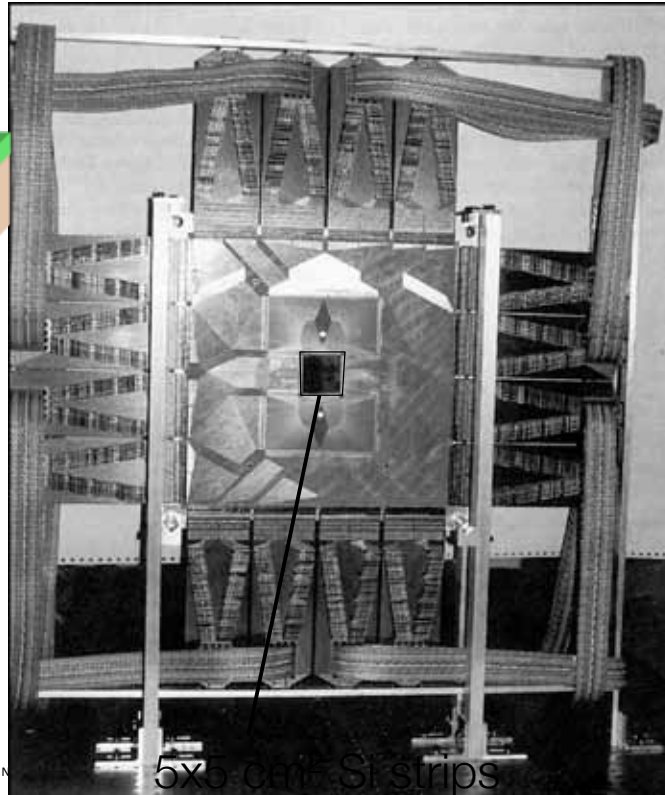
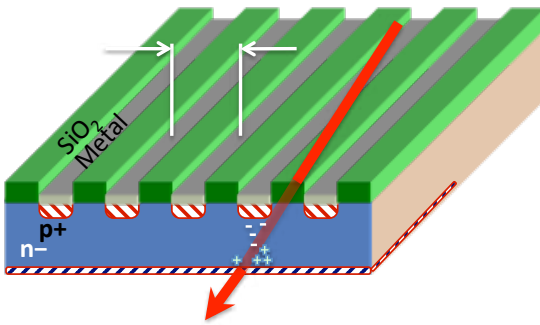


Archival Storage



Microelectronics-enabled Detectors

Silicon strip detector



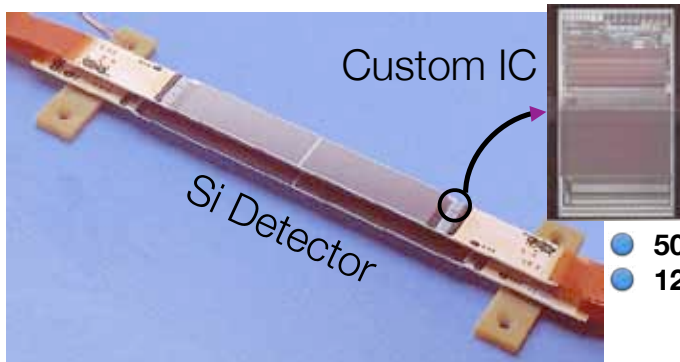
Silicon strip detector (1D)
for particle physics ca. 1984



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5x5 cm Si strips

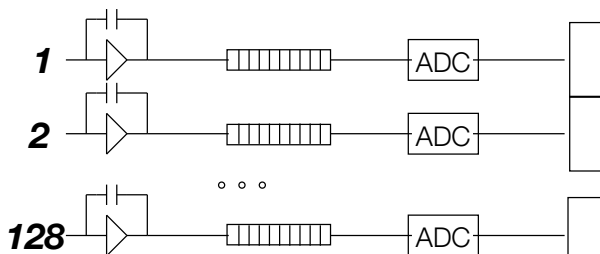
Followed by Custom ICs



- 50 μm pitch
- 128 channels



Charge sensitive
amplifier with
adjustable risetime



Analog pipeline Wilkinson ADC

8 Zero-suppressed
readout on 8-bit
parallel bus

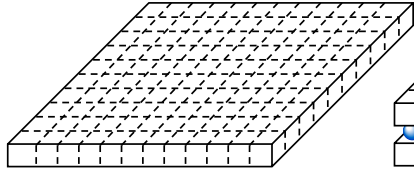


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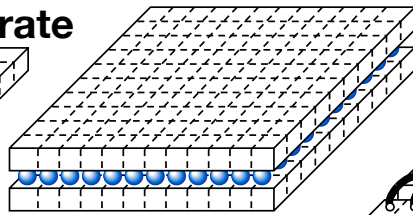


Further Options

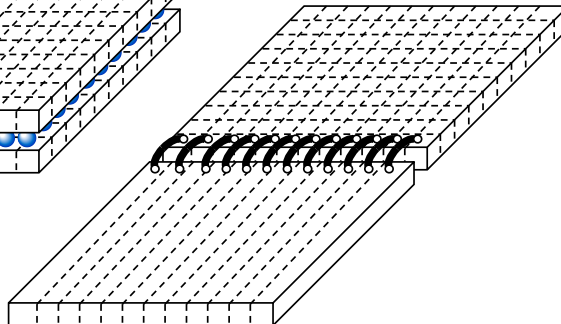
**Monolithic
sensor+readout
on same substrate**



Hybrid



**Sensor
+
Readout**



2D segmented Si

2D segmented Si attached to 2D segmented Si

2D segmented Si attached to 1D segmented Si or other electronics



LHC Pixel Detectors

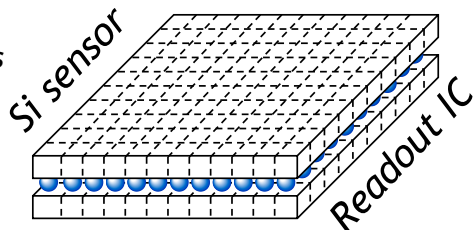


CMS

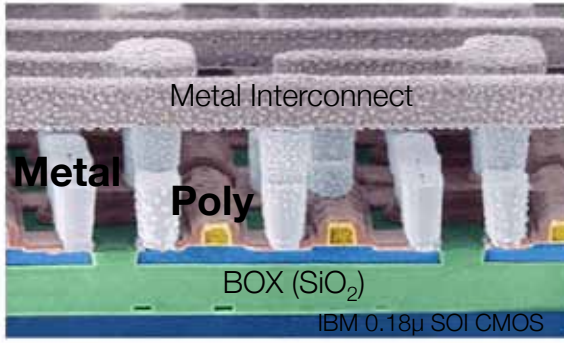


ATLAS

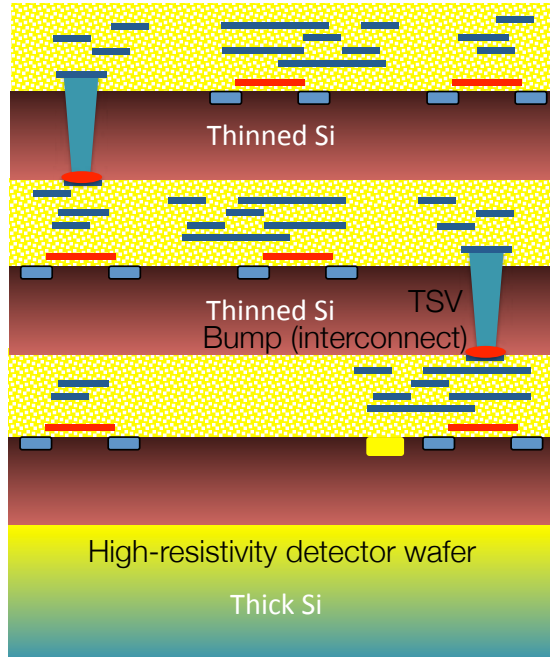
Large projects to develop hybrid pixels



R&D: SOI and 3D Integration



Oki SOI Process (KEK)



Si
BOX
High- ρ Si $\leq 300 \mu\text{m}$



(Direct Detection) Pixel Complexity

CCD on thick, high- ρ Si

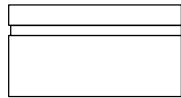


Size $10^2 - 10^3 \mu\text{m}^2$

$\frac{\text{H}}{\text{pix}}$ 0

ENC $10^0 - 10^1 e^-$

SOI on thick, high- ρ Si

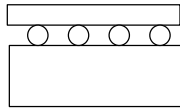


Size $10^2 - 10^3 \mu\text{m}^2$

$10^1 - 10^2$

$10^1 e^-$

Hybrid on thick, high- ρ Si

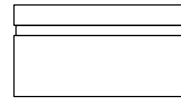


Size $10^4 \mu\text{m}^2$

$10^2 - 10^3$

$10^2 e^-$

3D on thick, high- ρ Si



Size $10^2 \mu\text{m}^2$

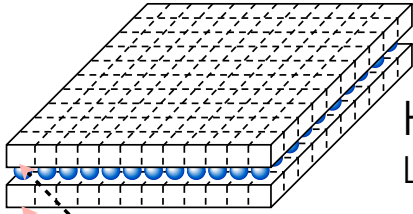
$10^1 - 10^2$

?

Disclaimer: ALS is a soft x-ray facility – ideal for Si (except for noise!)

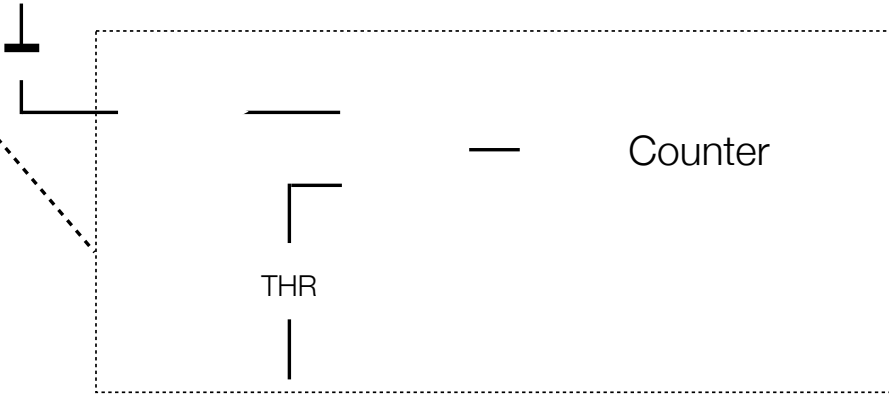


A parting, practical example



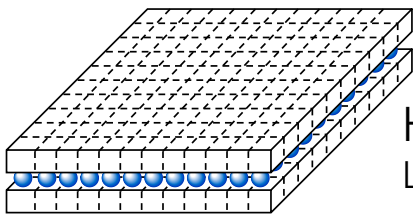
Hybrid pixel X-ray counting detectors
Large impact in macromolecular crystallography

Count hits above threshold

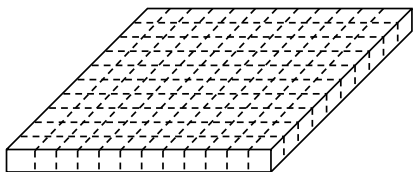


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A parting, practical example



Hybrid pixel X-ray counting detectors
Large impact in macromolecular crystallography

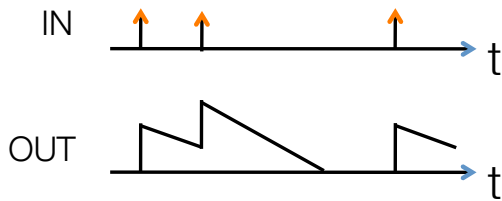
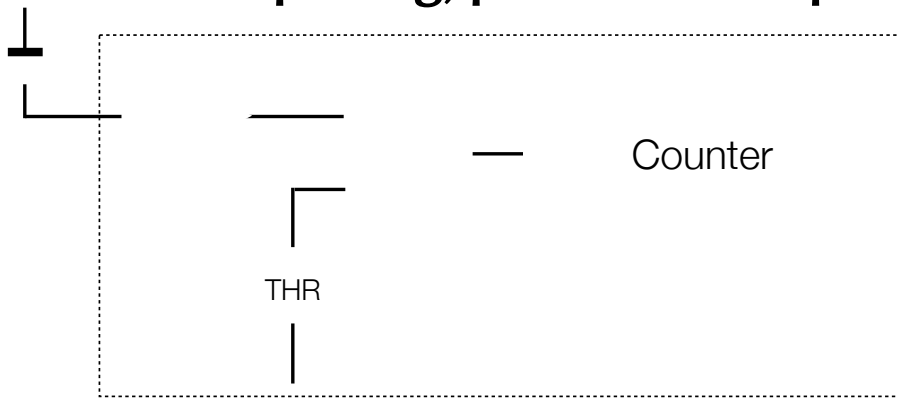


- 1 Silicon (in standard microelectronic thicknesses) starts to become transparent above 8 keV
→ Search for better sensors (hard to beat silicon)

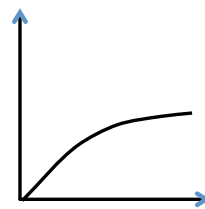


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A parting, practical example



② Count rate limitations → lose hits above a certain rate → “rate correction”

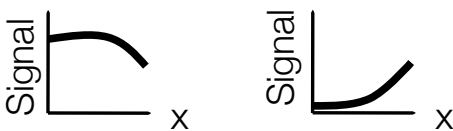


③ Pixel Size, Diffusion and Analog vs. Digital

Even a fully-depleted detector will have 5 – 10 μm RMS diffusion
(so there will be some charge sharing)



2 “large” digital (counting) pixels



Some region (depending on diffusion σ) where counting is complicated (double count? missed counts?)



3 “small” analog pixels

Diffusion spreads charge across pixels – but center-of-gravity can give sub-pixel (μm) position resolution (while adding noise!)



Summary (1)

- For a detector, the only useful thing a photon can do is create an electron
 - Note to accelerator people: the only useful thing an electron can do is create a photon
- Detection mechanisms
 - “Direct” (includes film, image plates, ...)
 - “Indirect” – usually via scintillator
- Sensor “properties” critical
 - Density (stopping power, σ_{PE} , ...)
 - Band gap, light yield, ...



Summary (2)

- Like parking spaces, “no lack of detectors, only lack of imagination”
 - Microelectronics-enabled detector development in particle physics starting to spill over into synchrotron radiation research
- Semiconductor detectors!
- DAQ, computing and processing!
- Si excellent for $E < 10$ keV (and benefits from commercial processing)
 - Other developments, e.g. involving avalanche multiplication, that there was no time to discuss
 - For higher energies, have candidate materials (GaAs, Ge, CdTe, ...) but need R&D
- Future will be detectors designed for experiments (not experiments designed for detectors)



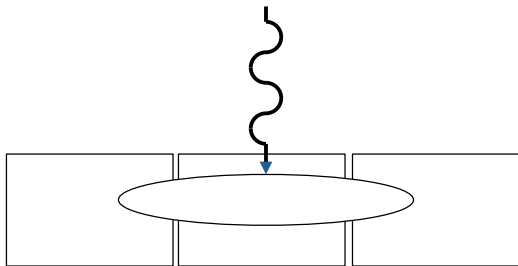
Summary (3)

● Fluctuations

- $0 \leq E_e \leq E_\gamma$ in “detector”
- Number ($N \propto E_e$) of secondary (tertiary) particles
- Electronic noise
 - Thermal
 - Faster is (generally) noisier
- Spatial resolution (PSF, MTF) (diffusion)
- Temporal resolution (noise is important)
- DQE
- Radiation damage (not discussed, but important)



In other words



- Photon incident at (0,0)
 - Probability Q.E. of creating a detectable* signal
 - Signal $\propto 1/\eta$
 - Photostatistics
 - Fano factor
 - Spatial resolution (PSF, MTF) (diffusion)
- *Detectable = f(Electronics)
 - DQE $\sim 1/[\text{Electronic}] \text{ Noise}$
- $\sigma(E) \sim F \oplus \text{Noise}$
- $\sigma(t) \sim \text{Noise}$

Understand the physics of detection
What you get is what you see
What (how) you see is complicated



Questions?

Grateful acknowledgements to:

ALS Experimental Systems Group
ALS Scientific Support Group
APS Beamline Technical Support Group
Electronic Systems Group
Integrated Circuit Design Group
MicroSystems Laboratory
National Center for Electron Microscopy
Physics Division
Engineering Division

